



The CERN Accelerator School



CERN Accelerator School

in collaboration with

MAX IV Laboratory

are organising a course on

**Vacuum for Particle Accelerators**

# INDUSTRIAL VACUUM APPLICATIONS

## - A VERY PERSONAL PERSPECTIVE

DR ANDREW CHEW

SATURDAY 10<sup>TH</sup> JUNE



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# CAS - VACUUM FOR PARTICLE ACCELERATORS

DRAFT PROGRAMME FOR VACUUM FOR PARTICLE ACCELERATORS												
6-16 June, 2017, Lund, Sweden												
Time	Tuesday 6 June	Wednesday 7 June	Thursday 8 June	Friday 9 June	Saturday 10 June	Sunday 11 June	Monday 12 June	Tuesday 13 June	Wednesday 14 June	Thursday 15 June	Friday 16 June	
08:30	A R R I V A L D A Y  LUNCH  S. Sgobba Materials & Properties II: Thermal & Electrical Characteristics  S. Calatroni TEA Materials & Properties III: Mechanical Behaviour  C. Garion Buffet	Opening Talks	Materials & Properties IV: Outgassing	Getter Pumps	Industrial Vacuum Applications		Surface Characterisation	Transport to Max IV Lab	Controlling Particles/Dust in Vacuum Systems	Vacuum Design Aspects		
09:20			P. Chiggiato	E. Maccallini			R. Valizadeh		L. Lilje	H. Reich-Sprenger	D	
09:30			Introduction to Machine Parameters	Vacuum Gauges I	Ion Pump Technology for Particle Accelerators	Vacuum Gauges II		Interactions between Beams and Vacuum System Walls	Seminar Max IV Laboratory	Beam Induced Radioactivity & Radiation Hardness	Manufacturing & Assembly for Vacuum Technology	E
10:20			P. Tavares	K. Jousten	M. Audi	K. Jousten	E	R. Cimino	M. Grabski	F. Cerutti	S. Madhot	A
11:00			COFFEE	COFFEE	COFFEE	COFFEE	X	COFFEE	COFFEE	COFFEE	COFFEE	R
11:00			Fundamentals of Vacuum Technology	Mechanical Vacuum Pumps	Introduction to Cryogenics	Beam Induced Desorption	C	Surface Cleaning & Finishing	Seminar ESS Spallation Source Vacuum System	Radiation Damage and its Consequence	The Real Life of Operation	T
11:50							U					U
12:00			E. Al Dmour	H. Barfuss	S. Claudet	O. Malyshev	S	M. Taborelli	M. Juni Ferreira	M. Brugger	V. Baglin	E
12:00			Impedance & Instabilities	Computation for Vacuum System of Accelerators	Cryo- pumping	Beam-Gas Interaction	I	Thin-Film Coating		Control & Diagnostic	Challenges for Vacuum Technology of Future Accelerators	D
13:00			R. Wanzenberg	R. Kersevan	V. Baglin	M. Ferro Luzzi	N	P. Costa Pinto		P. Gomes	J. Jimenez	A
14:30			LUNCH	LUNCH	LUNCH	LUNCH		LUNCH	LUNCH	LUNCH	LUNCH	Y
14:30			Materials & Properties I: Introduction						Visit to Max IV		Tutorial Work	
15:20			S. Sgobba	Tutorial	Tutorial	Tutorial		Tutorial	15:30	Tutorial		
15:30			Materials & Properties II: Thermal & Electrical Characteristics						15:30		Closeout	
16:20			S. Calatroni						Visit to ESS			
17:00			TEA	TEA	TEA	TEA		TEA		TEA	TEA	
17:00			Materials & Properties III: Mechanical Behaviour	Tutorial Work	Tutorial Work	Tutorial Work		Tutorial Work		Tutorial Work	Closing Remarks	
17:50			C. Garion									
19:30		Buffet	Dinner	Dinner	Dinner	Dinner	Dinner	Dinner	Dinner	Dinner	Special Dinner	

# ABSTRACT

- *The market segmentation of the vacuum industry includes a wide range of applications; from microelectronics processing to food packaging, to the 'Analytical' sector*
- *As well as giving an overview of the vacuum industry, we will focus on some specific examples including semiconductor manufacturing, metallurgy and the historical evolution of vacuum pump requirements in Liquid Chromatography Mass Spectrometry.*
- *This will be discussed in relation a wide range of factors including; applicable pump type, crucial characteristics and communications protocols. Future trends will be discussed*

# CONTENTS

1. A brief biography
2. Some definitions
3. The Vacuum Market Segmentation
4. Some applications examples
  - Micro-electronics/Semiconductor
  - Steel
  - Liquid Chromatography Mass Spectroscopy
  - CPI
  - Food
  - Sterilization
7. Common themes
8. Future
9. Summary

FIRSTLY.....

## EXPERIMENT ON CHEW'S SECOND THEOREM



WE SHALL RETURN TO THIS LATER

# Biography



1968



1995

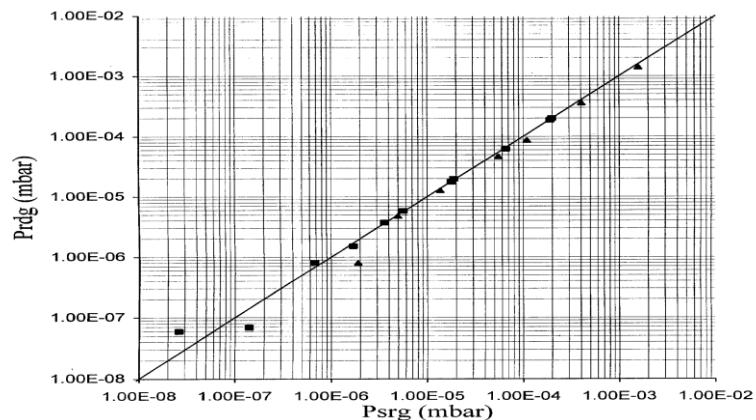
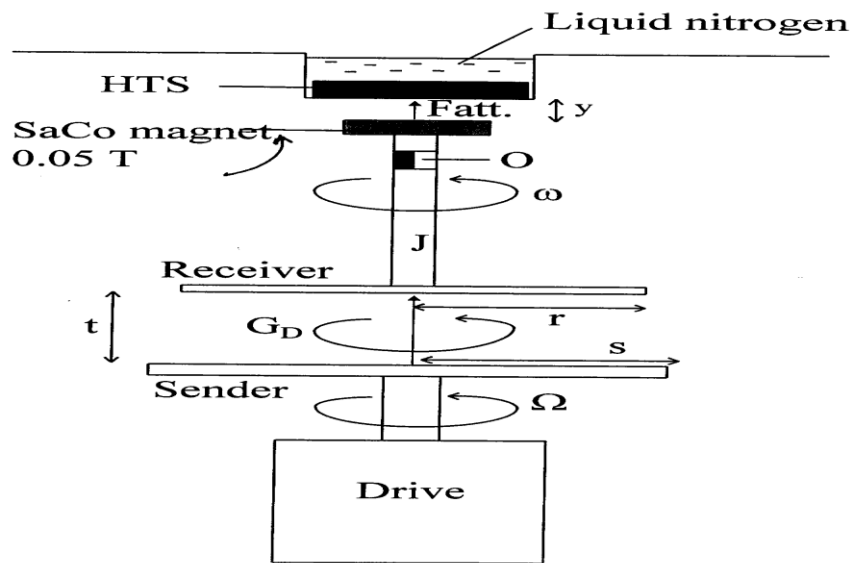
1986





# SHORT BIOGRAPHY - ROTATING DISC GAUGE

Measures molecular torque developed between coaxial discs direct



1989-1995

## Application of a high critical temperature superconductor bearing for high vacuum measurement

A. D. Chew<sup>1</sup>  
 Edwards High Vacuum International, Crawley RH10 2LW, United Kingdom  
 A. Chambers  
 Department of Physics, University of York, York YO1 5DD, United Kingdom  
 A. P. Troup  
 Edwards High Vacuum International, Crawley RH10 2LW, United Kingdom  
 (Received 13 September 1996; accepted 17 March 1997)

A novel and ultrahigh vacuum compatible, high critical temperature superconductor suspension is described in its application to a rotating disc vacuum gauge. The noncontacting and robust suspension comprises a permanent magnet (and attached disc) suspended freely in a vacuum and below a liquid nitrogen cooled YBaCuO<sub>7-x</sub> pellet which is held outside the vacuum chamber. This configuration suspends a fiber suspension. Molecular torque developed from a high speed disc accelerates the suspended disc and facilitates a measurement of total pressure. The effect of the superconductor suspension (analogous to that of the spinning rotor gauge) is about  $5 \times 10^{-8}$  mbar, nitrogen equivalent. After 30 h the offset reduced by up to 21% of its initial value. In the range  $1.6 \times 10^{-5}$ – $3.6 \times 10^{-7}$  mbar, the pressure measured using this device was within  $\pm 20\%$  of that measured by a spinning rotor gauge; at lower pressures the agreement with an ionization gauge degraded to  $\approx 80\%$ . Improvements in pellet structure reduce internal losses in the bearing and in the offset term, by a factor of 10, and should enable measurements in ultrahigh vacuum. © 1997 American Vacuum Society. [S0734-2101(97)1003-X]

### 1. INTRODUCTION

The exploitation of the phenomenon of molecular drag as a means for vacuum measurement is currently most usefully made by the spinning rotor gauge<sup>1</sup> (SRG), although recent studies have been undertaken with an electrostatic suspension.<sup>2</sup> An extensive re-examination of the original rotating disc vacuum gauge (RDG) configuration, the forerunner of the SRG, has been conducted by the authors.<sup>3,4</sup> This work illustrated both the potential of the RDG and its limitations when using a fiber suspension, chiefly: sensitivity to vibrations, noncontinuous measurements, and a lower measurement limit in the low  $10^{-7}$  mbar range. In an attempt to surmount these limitations, a RDG has been developed which utilizes a high critical temperature superconductor (HTS) bearing suspension. The construction was ostensibly designed as a technique for the measurement of the intrinsic drag torques of HTS bearings<sup>5</sup> but its application for the measurement of vacuum pressure was recognized and pursued.

### 2. THEORY

The RDG has been described in detail previously<sup>3,5</sup> and its essential features are shown in Fig. 1. The instrument is housed in an UHV system and consists of a unit *D* driving a sender disc *S*, of radius *s*, at radian frequency  $\Omega (=2\pi f_s)$  and a coaxial and parallel receiver disc *R*, of radius *r*, which is held at a distance *t* above it. A suspension system *J* carries the receiver and an optical arrangement for the measure-

ment of the radian frequency  $\omega (=2\pi f_r)$  of the suspension. The suspension is held by the attractive force  $F_{att}$  established between a permanent magnet *M* and a liquid nitrogen cooled HTS pellet which is located outside the vacuum system. The (noncontacting) magnet-pellet distance is *y*.

In molecular flow the accelerating molecular torque  $G_D$  developed by the sender<sup>6</sup> and communicated by molecular drag, is

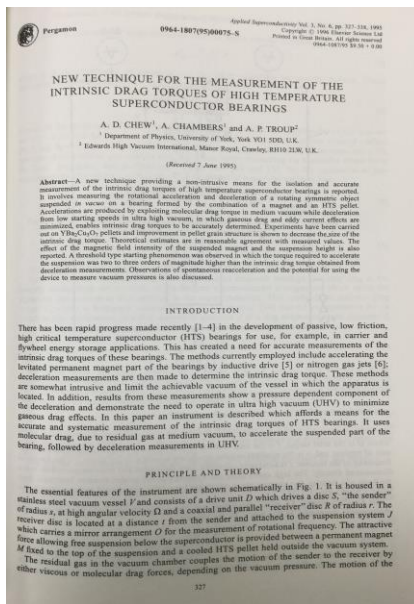
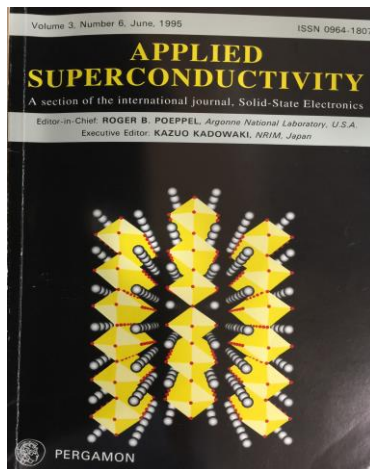
$$G_D = \sigma \alpha I \omega^2 \left( \frac{\pi M}{8kT} \right)^{1/2} p, \quad (1)$$

where  $R_0$  is the gas constant, *T* the thermodynamic temperature, *M* the molar mass, and *p* the pressure of the residual gas,  $\sigma$  is the tangential momentum accommodation coefficient of gas molecules on the receiver surface, previously measured as unity for a smooth surface,<sup>7</sup>  $\epsilon$  is the edge effect loss factor ( $0 < \epsilon < 1$ ) accounting for molecules which leave the discs' interpace,<sup>8</sup> typically  $\epsilon = 0.65$ . The response of the suspension about the vertical axis (assuming  $dI/dt = 0$ ) is governed by

$$G = I \dot{\omega}, \quad (2)$$

where *G* is the total torque, *I* is the moment of inertia of the suspension about the vertical axis, accurately determined by mass and dimension measurements, and  $\omega$  is its resultant angular acceleration, measured directly. There are several sources of drag<sup>9</sup> in the HTS bearing giving rise to a decelerating torque. Frequency independent intrinsic drag  $G_I$  results from asymmetries in the magnet/superconductor arrangement and acts radially.  $G_M$  is the molecular drag torque due

<sup>1</sup>Electronic mail: andrew.chew@edwards.bec.com



$$I\dot{\omega} = G_D - G_I - G_M - G_E$$

- $G_D$  ~ pressure
- $G_I$  suspension asymmetries
- $G_M$  molecular drag
- $G_E$  Eddy current drag

# INDUSTRIAL VACUUM APPLICATIONS – DICTIONARY DEFINITIONS

## Industrial

ADJECTIVE

relating to or characterized by industry

Synonyms: manufacturing, factory, commercial, business, trade

## Vacuum

NOUN

1. a region containing no matter; free space
2. a region in which gas is present at a low pressure
3. the degree of exhaustion of gas within an enclosed space: a high vacuum, a perfect vacuum

any region below atmospheric pressure

Synonyms: empty space, emptiness, void, nothingness, vacuity, vacancy, voidness, nihility

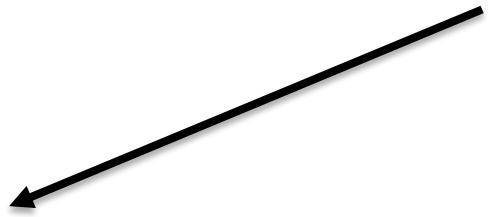
## Applications

NOUN

the special use or purpose to which something is put:

Synonyms: utilization, aptitude, suitability, pertinence, solicitation, petition, assiduity, industry, persistence, perseverance

Dictionaries  
are not  
always very  
good



# THE VACUUM MARKET SEGMENTATION - ISVT

International Statistics on Vacuum Technology  
 JVIA (Japan Vacuum Industry Association)  
 AVEM (Association of Vacuum Equipment Manufacturers)  
 EVTA (European Vacuum Technology Association)  
 in co-operation with  
 SEMI (Semiconductor Equipment and Materials)

## Vacuum Market Segmentation

Rough Vacuum	Process Vacuum	Industrial Vacuum	Semiconductor Process Vacuum	Thin Film Deposition (non-Semiconductor)	Solar	Instrumentation Manufacturers	R&D
<u>Markets</u> - Packaging (except food) - Central Vacuum - Printing and Paper Handling - Pick and Place - Conveying - Moulding - Air sampling - Medical	<u>Markets</u> - Chemical (Bulk, Fine,...) - Petrochemical - Pharmaceutical - Plastics (Extrusion,...) - Food - Beverage - Textile - Paper - Ceramics - Freeze drying - Energy (Wind, Nuclear, Stream Turbines,...) - Central Vacuum (Batteries,...)	<u>Markets</u> - Vacuum Metallurgy (Metal Degassing, Melting, Re-melting, E-beam welding, casting,...) - Vacuum Heat Treatment (Brazing, Carburising, Nitriding, Quenching,...) - Laser Technology - Electron Tubes - TV Tubes - Lamps and Bulbs - Industrial leak detection - Refrigeration and Air Conditioning - Automotive (Dehydration, Charging and Test) - Electrical (Encapsulation,..)	<u>Markets</u> - Silicon - Semiconductor - Compound Semiconductor (LEDs,...) - TFT-LCD Displays - MEMS - Crystal Pulling  <i>Please note: Above includes both Process Equipment Manufacturers and End Users for PVD, CVD, Etching, Ion Implantation, MBE</i>	<u>Markets</u> - Glass/Web/Optical Coating - Optical Data Storage (CD, DVD, Hi Def Disk,...) - Magnetic Data Storage (HDD) - Thin Film Heads - Surface Coating (wear protection, decorative, ...) - Display Coatings (OLED, FED, PDP, SED,...)	<u>Markets</u> - Photovoltaic Solar (c-Si & Thin-Film Deposition, Laminating,...) - Thermal Solar (Water Heaters,...) - Crystal Growth (Re-melt, ...)	<u>Markets</u> - Mass Spectrometers - Electron Microscopes - Metrology/ Inspection/ Defect Review systems for Semiconductor including Focused Ion Beam systems and Electron Beam systems - Surface Analysis - Gas Analysis - X-Ray Analysis - MRI and NMR - Sample preparation (Driers, Centrifuges, Concentrators,...) - Leak Detectors	<u>Markets</u> - Universities - Government Labs - Scientific Research Laboratories - Space Simulation
<b>Typical operating pressure (mbar)</b>							
<b>&gt; 1</b>	<b>&gt; 10<sup>-2</sup></b>	<b>10<sup>-2</sup> - 10<sup>-6</sup></b>	<b>1 - 10<sup>-8</sup></b>	<b>10<sup>-3</sup> - 10<sup>-8</sup></b>		<b>10<sup>-6</sup> - 10<sup>-10</sup></b>	<b>10<sup>-2</sup> - 10<sup>-11</sup></b>

- |          |   |       |   |
|----------|---|-------|---|
| PVD:     | Physical Vapour Deposition                  | CD:   | Compact Disk  |
| CVD:     | Chemical Vapour Deposition                  | DVD:  | Digital Video Disk  |
| MBE:     | Molecular Beam Epitaxy                      | OLED: | Organic Light Emitting Diode (or OLED: Organic Electro Luminescent Display) |
| MEMS:    | Micro Electro Mechanical Systems            | FED:  | Field Emission Display  |
| TFT-LCD: | Thin-Film Transistor Liquid Crystal Display | PDP:  | Plasma Display Panel  |
| SED:     | Surface Emission Display                    | MRI:  | Magnetic Resonance Imaging  |
| HDD:     | Hard Disk Drive                             | NMR:  | Nuclear Magnetic Resonance  |

This Vacuum Market Segmentation Chart was developed by the Working Group of the International Statistics on Vacuum Technology Program (ISVT), and is published with their permission. Organisations that participate in the program are the Association of Vacuum Equipment Manufacturers International (AVEM), the Japan Vacuum Industry Association (JVIA), the European Vacuum Technology Association (EVTA), and the Semiconductor Equipment and Materials International (SEMI).

Version 2010.0, Hangzhou, China, September 24th 2009



# ISVT PARTICIPATING COMPANIES

**International Statistics on Vacuum Technology**  
 JVIA (Japan Vacuum Industry Association)  
 AVEM (Association of Vacuum Equipment Manufacturers)  
 EVTA (European Vacuum Technology Association)  
 in co-operation with  
 SEMI (Semiconductor Equipment and Materials)

## ISVT 2016 Participating companies

AVEM	JVIA	EVTA
1 A&N	1 Anest Iwata	1 Aerzener Maschinenfabrik
2 Brooks Automation	2 Anlet	2 Agilent Technologies
3 DigiVac	3 Canon Anelva	3 Edwards
4 Drivac	4 Choshu Industry	4 GD Deutschland
5 GD Welch Technology	5 Cosmotec	5 GD Nash
6 GNB	6 Diavac	6 Gebr. Becker
7 Lesker	7 Ebara	7 Körting
8 Inficon	8 Fuji Technology	8 Oerlikon Leybold Vacuum
9 Mass-Vac	9 Green Tec	9 Pfeiffer Vacuum
10 Rocky Brook Associates	10 Hakuto	10 PIAB
11 Shi-APD Cryo	11 Hitachizosen	11 Robuschi
12 Teledyne Hastings Instruments	12 Irie Koken	12 Sterling Fluid Systems
13 Televac	13 Jeol	13 VACOM
14 Tuthill Vacuum Systems	14 Kashiyama	
15 U-C Components	15 Matamura Oil Research	
16 Vacuum Research Corporation	16 Mitsubishi Cable Industries	
17 Verity Instruments	17 Musashino Engineering	
	18 Neis	
	19 Okano Works	
	20 Oporun	
	21 Osaka Rasenkan Kogyo	
	22 Osaka Vacuum	
	23 Rigaku	
	24 Sato Vac	
	25 Shibaura Eletec	
	26 Shimadzu	
	27 Shimadzu Emit	
	28 Shinko Seiki	
	29 Shinmaywa Industries	
	30 SMC	
	31 Sumitomo Heavy Industries	
	32 Taiko Kikai Industries	
	33 Taisei Kinzoku Kogyosho	
	34 Tokyo Electronics	
	35 Toyama	
	36 Ulvac Cryogenics	
	37 Ulvac Kiko	
	38 Ulvac Tecno	
	39 Ulvac	
	40 V Tex	
	41 Wakaida Science	

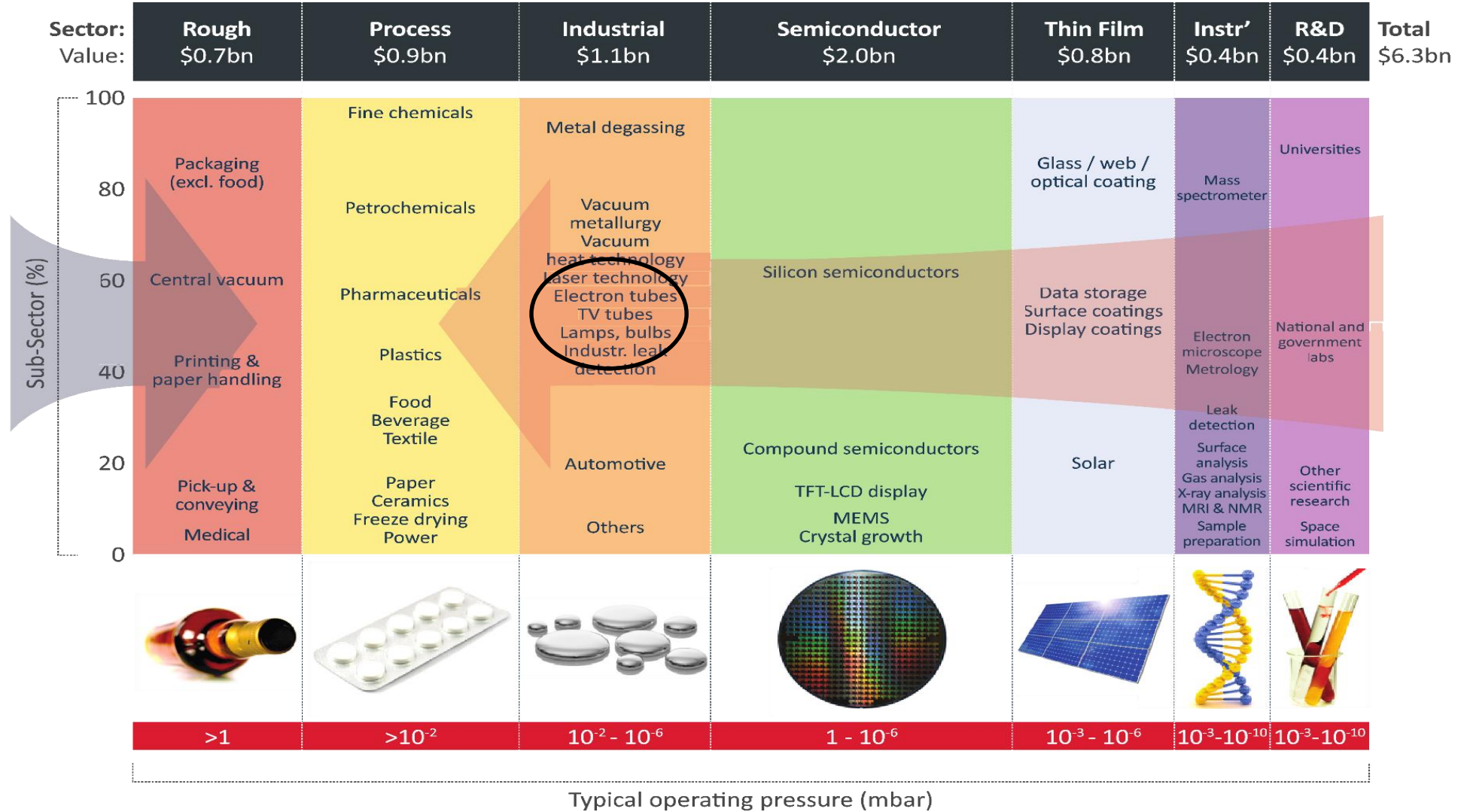
Not all suppliers participate

Ulrike Mätje 2016-10-13



# THE VACUUM WORLD

Dynamic range = 15 orders!!



Source: ISVT and Atlas Copco

# HOW DOES THIS MARKET COMPARE?

Vacuum @ \$9B

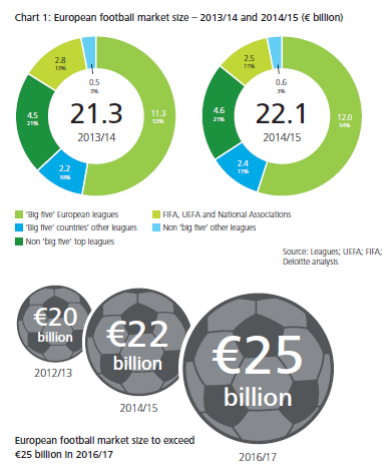
European football ~\$30B

Oil ~ \$2,000B

Scotch Whiskey ~ \$3B

Automotive ~ \$620B

Film Box Office ~ \$38B



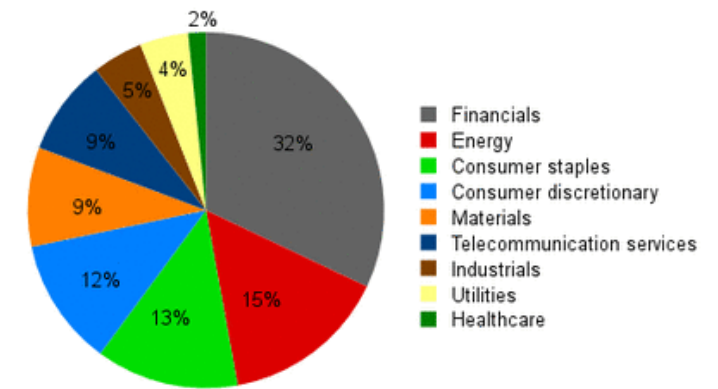
[https://en.wikipedia.org/wiki/List\\_of\\_countries\\_by\\_GDP\\_\(nominal\)](https://en.wikipedia.org/wiki/List_of_countries_by_GDP_(nominal))

Global GDP = ~\$75,000,000M

Agriculture	Industrial	Services
6%	31%	64%

[https://en.wikipedia.org/wiki/List\\_of\\_countries\\_by\\_GDP\\_sector\\_composition](https://en.wikipedia.org/wiki/List_of_countries_by_GDP_sector_composition)

<https://www2.deloitte.com/content/dam/Deloitte/uk/Documents/sports-business-group/deloitte-uk-annual-review-of-football-finance-2016.pdf>

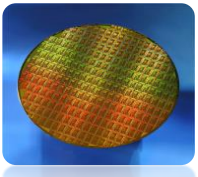
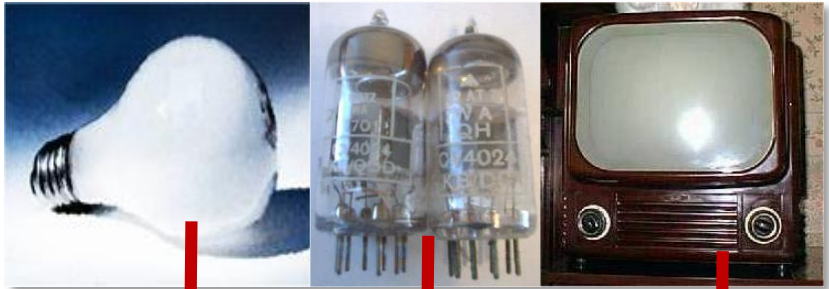


Source: iShares.

<https://www.statista.com/topics/964/film/>



# APPLICATIONS....OVER THE YEARS



[https://en.wikipedia.org/wiki/Electron\\_microscope](https://en.wikipedia.org/wiki/Electron_microscope)

# VACUUM PUMPS: FROM VERY SMALL TO VERY BIG

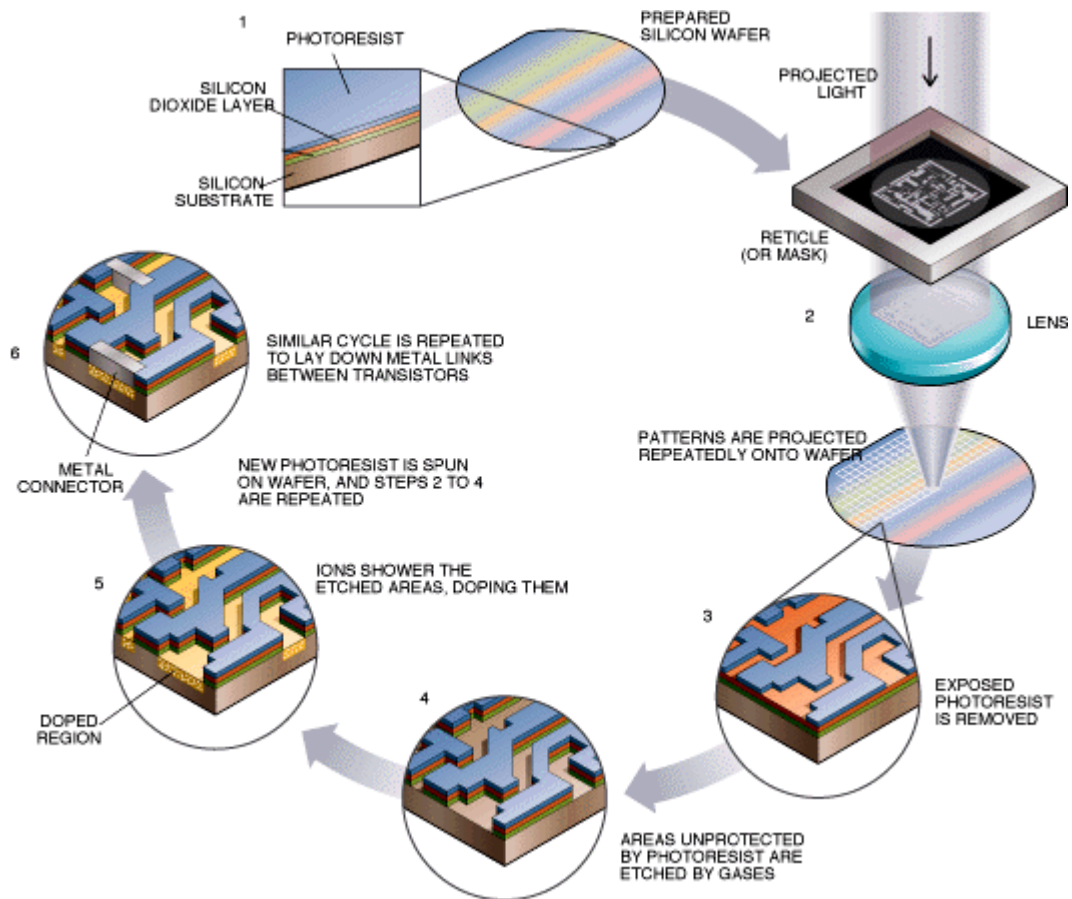




# SOME APPLICATIONS EXAMPLES

- Microelectronics
- Steel
- Liquid Chromatography Mass Spectroscopy
- CPI
- Food
- Microscopy
- Sterilization

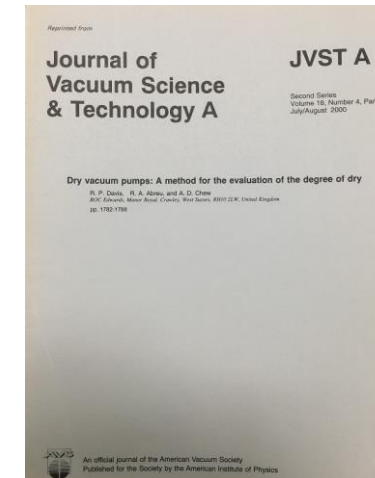
# MICROELECTRONICS/SEMICONDUCTOR



Wafer pulling

He, Ar

Large primary pumps

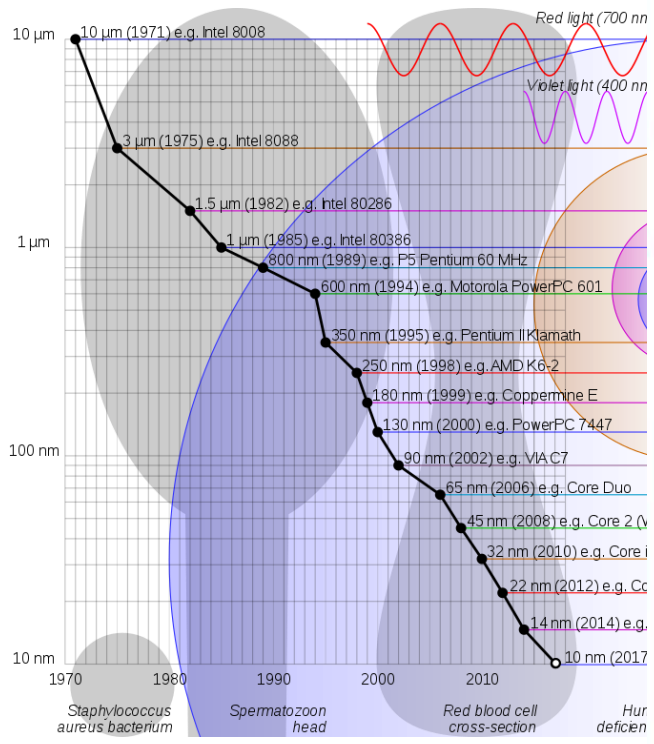


[https://www.edwardsvacuum.com/Semiconductor\\_Processing/](https://www.edwardsvacuum.com/Semiconductor_Processing/)

[https://en.wikipedia.org/wiki/Semiconductor\\_device\\_fabrication#/media/File:Comparison\\_semiconductor\\_process\\_nodes.svg](https://en.wikipedia.org/wiki/Semiconductor_device_fabrication#/media/File:Comparison_semiconductor_process_nodes.svg)

# SEMICONDUCTOR

Semiconductor industry is driving towards logic dimensions of 7nm = 70 Å



**EDWARDS G450C**

## 450mm

Rethinking the approach to higher 450mm process gas flows: a case study

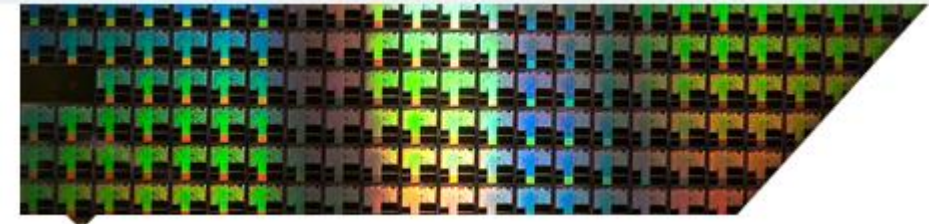
**THE SITUATION**  
As wafer diameter increases to 450mm, surface area increases by 2.25x times and process gas flows are expected to grow by up to 3x times.

**OUR SOLUTION**  
Requires about 1000cc of a 1000bar (2.25 psi or 5 kPa or 0.15 Torr) for the primary set of connections after the vacuum pump.

**TRADITIONAL RESULTS**  
The US of about 8.13% of total flow. At a 300cc flow of 2 atm, N<sub>2</sub> would require the addition of 200 cc of N<sub>2</sub> to the exhaust of the pump. If 30 atm comes from the pump purge another 100 cc must be added. If 100 cc of additional capacity were compressed, \$200,000 and N<sub>2</sub> costs \$0.5 per liter.

**THE BENEFITS**  
INTEGRATING MONITORED CONNECTIONS INTO AN INTEGRATED SUBSTRATE PACKAGE CAN PROVIDE SAFE COST REDUCTION AND RESOURCE CONSERVATION

COMPONENT	QTY	UNIT PRICE	TOTAL PRICE
Hybrid H <sub>2</sub> /O <sub>2</sub> /N <sub>2</sub> Flow	1	\$88,000	\$88,000
...	...	...	...



[https://en.wikipedia.org/wiki/Semiconductor\\_device\\_fabrication#/media/File:Comparison\\_semiconductor\\_process\\_nodes.svg](https://en.wikipedia.org/wiki/Semiconductor_device_fabrication#/media/File:Comparison_semiconductor_process_nodes.svg)

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# 1980'S SEMICONDUCTOR – 'GAME CHANGING' DRY PUMP

[http://www.edwardsvacuum.com/newsletters/vacuum\\_particles/0109/pArticles\\_files/fun\\_fact\\_henry\\_wycliffe.pdf](http://www.edwardsvacuum.com/newsletters/vacuum_particles/0109/pArticles_files/fun_fact_henry_wycliffe.pdf)

Feature

WORLD PUMPS May 2009

2009

Corrosive handling

## Twenty five years' dry vacuum pumping

Dr Andrew Chew, market and applications development manager at Edwards, looks at the important development of the dry, oil-free vacuum pump, which solved the back streaming problems that had previously plagued major industry sectors for years – metallurgy, vacuum drying and semiconductor manufacture among them.

In 1955, a young Polish man, unable to return home after the war, decided to embark on an engineering degree in London. Following his graduation he joined a small family business called Edwards. What no-one could possibly foresee was that this engineer would go on to invent a radical new technology – the dry pump – that would become the foundation for a legacy of products for one of the world's largest engineering firms.

Henry Wycliff was born in 1925 in Katowice in Upper Silesia. He was 14 when the Germans invaded Poland in 1939. After the war, he settled in the UK where he became an engineering student in 1948 and gained a BSc (Eng) with second-class honours.

**Need for vacuum**  
In August 1953 Henry Wycliff, now having changed his surname to Wycliffe,

Figure 1: Henry Wycliffe with an Edwards dry pump.

www.edwardspumps.com 0202 1762106 © 2009 Elsevier Ltd. All rights reserved.

**Oil-free pumps**  
At the time of the BOC acquisition, Wycliffe had been with Edwards for some 20 years and was head of the mechanical pump section. His role included looking at further development of pumps in order to increase the variety and size, providing support to marketing and specifying pumping systems for various applications.

Engineers at Edwards were encouraged to come up with innovative ideas and they kept in touch with what was happening in the field, from discussing problems with service engineers to following competitors and studying their patents.

Wycliffe identified that there was a need for oil-free pumps in the metallurgy industry, where quantities of dust are carried from the vacuum furnaces, and for vapour extraction and recovery in the chemical industry, where the pumped gas needs to be extracted uncontaminated and compressed for reuse.

With diffusion and rotary pumps, a problem arose from migration (back diffu-

rotary pumps, there was not enough displacement for the size and weight of this design.

**Claw mechanism**  
Wycliffe instead looked at the much older Northey claw principle, developed by a Mr. Northey in the UK around 1929 as an internal combustion engine. He called it the **Patent 1980**.

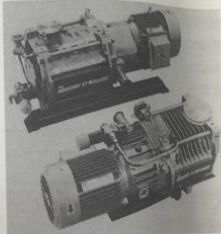
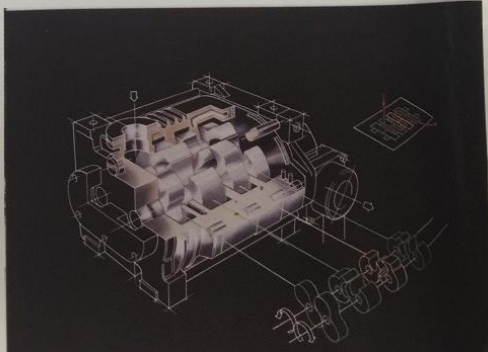


Figure 2: One of the original Edwards dry pumps – the Drystar.



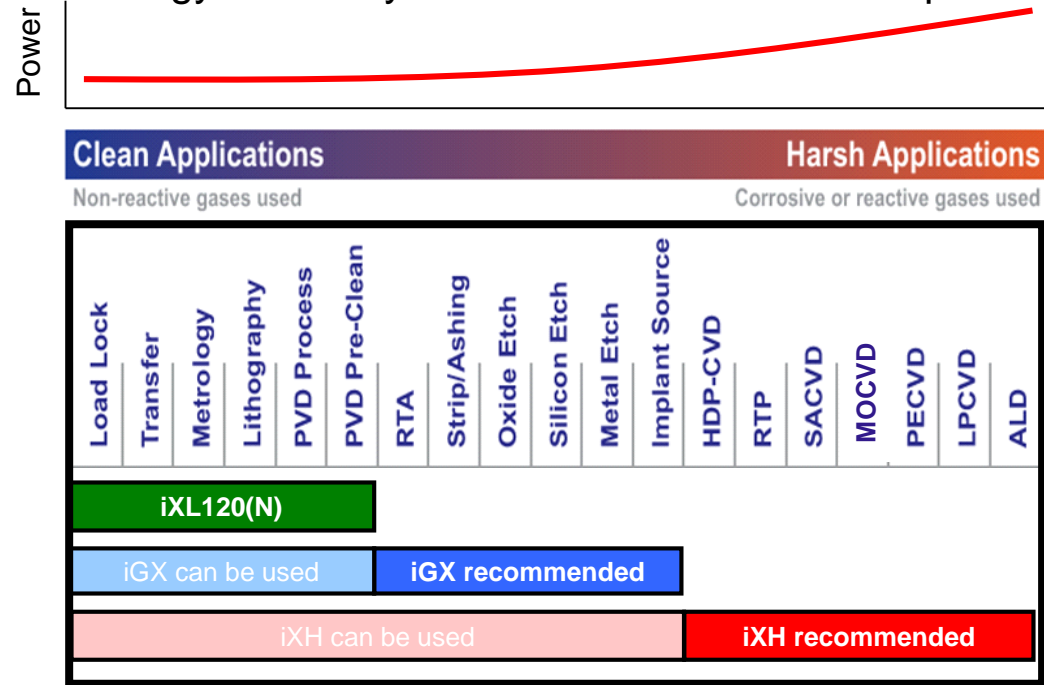
Henryk Wycliffe 2017



# PROCESS SEGMENTATION AND POWER REQUIREMENTS

Part of the energy balance offered across all semiconductor applications

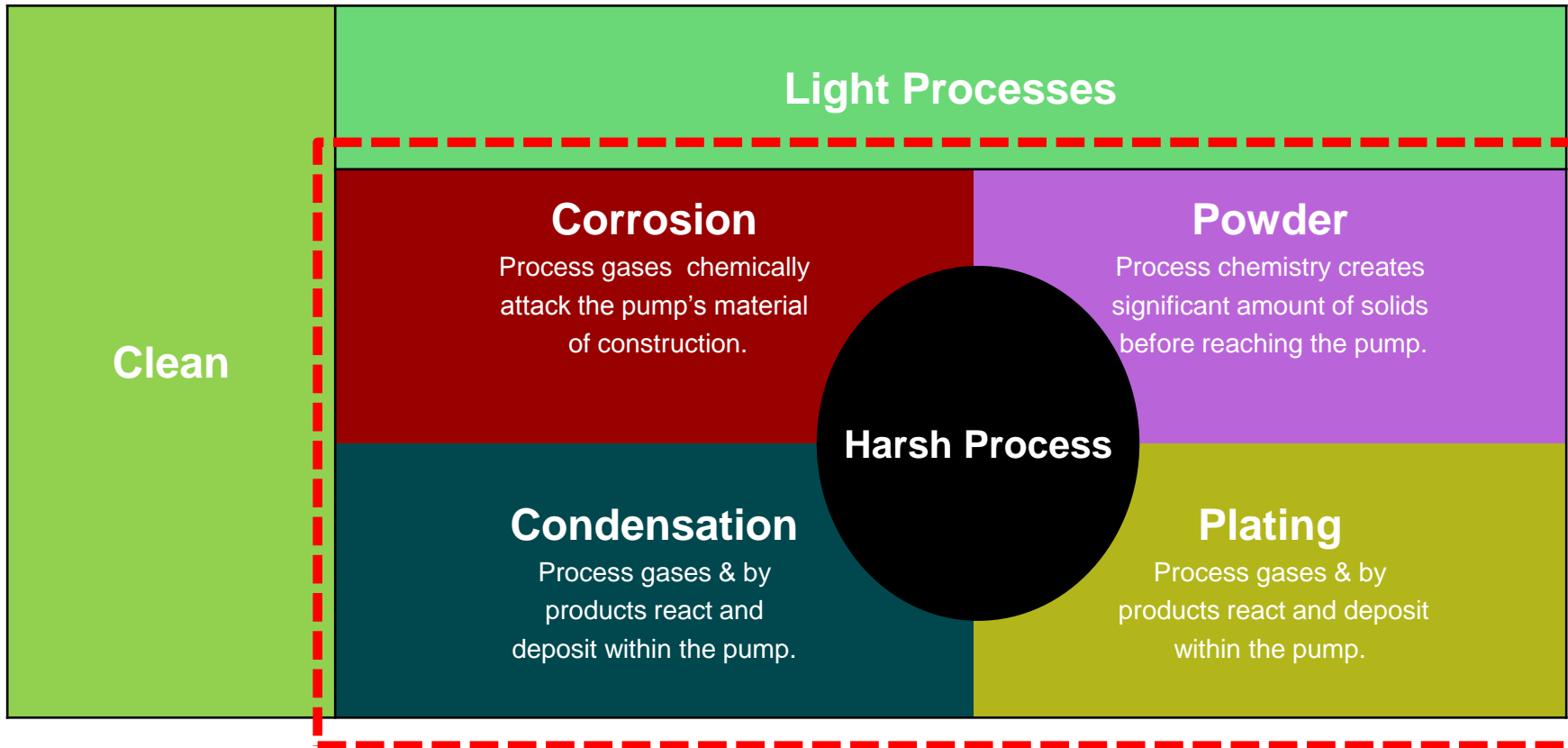
Maximises energy efficiency across the fab without compromising reliability on process



- “No Wafer Scrap” policy is king
- Some processes require high temperature = higher power
- The application requirements dictate the required pump

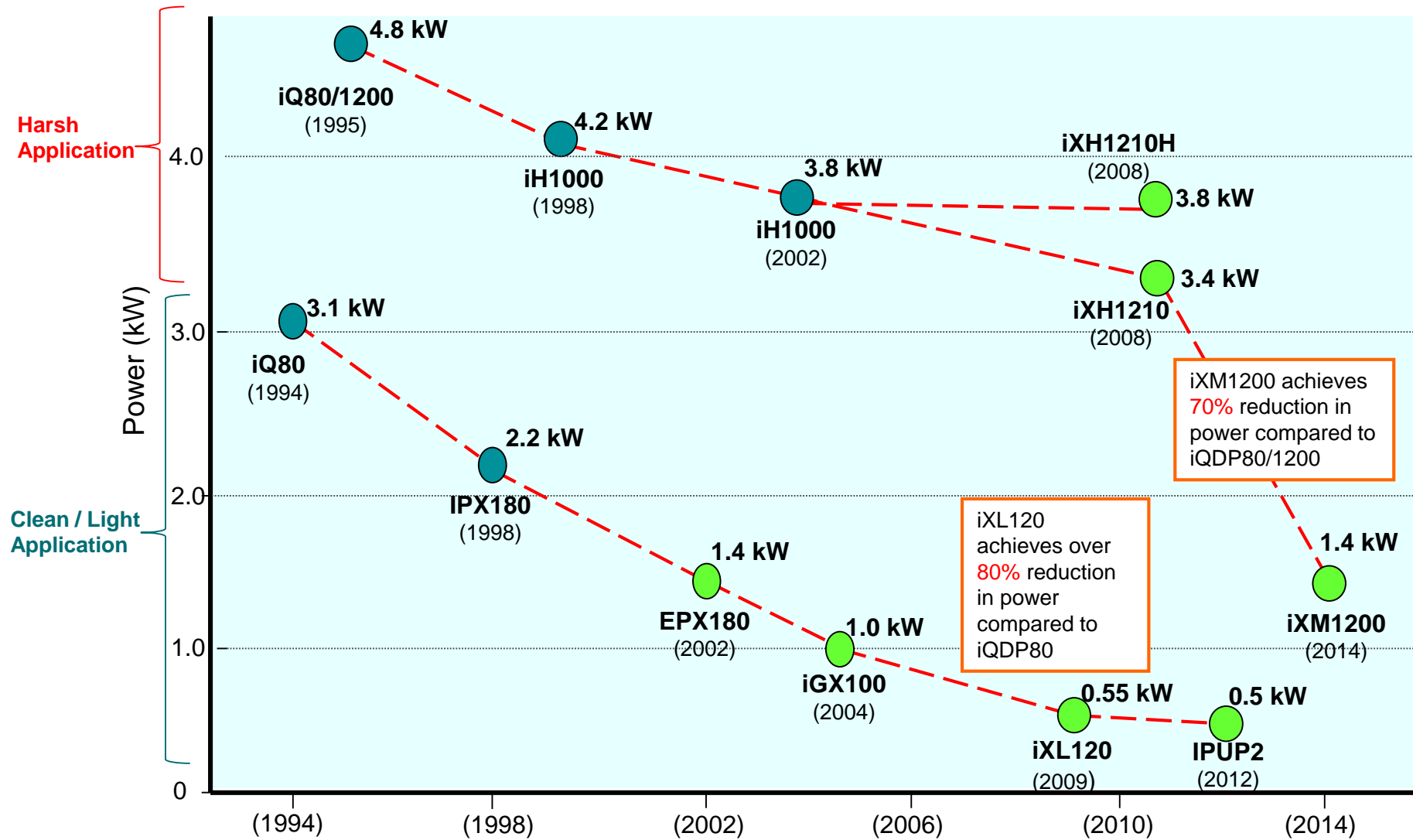
- 1 kW power reduction per pump equates to ~\$1,000 annual savings at \$0.12 / kW-h.
- However, a single pump failure can more than obliterate any savings in energy through lost wafers and tool downtime.

# CLASSIFICATION OF SEMICON APPLICATIONS



- Low energy solutions can be optimized for light to medium duty applications with little to no risk of process induced failures.
- Harsh duty applications require more robust pumps with application specific solutions.

# EDWARDS' DRY PUMP POWER REDUCTION TREND



# STEEL DEGASSING – HYDROGEN PUMPING

1,000,000 m<sup>3</sup>h<sup>-1</sup> at 0.5 mbar for Chong Qing Steel Group Co. (Chongqing, China)

## Mechanical vacuum pump system for steel degassing

Vacuum Degassing (VD) and Vacuum Oxygen Decarburisation (VOD) are often used in the production of speciality steel alloys. They are used to reduce the levels of hydrogen, carbon and other impurities during the secondary steel making process.

Historically large multi-stage steam ejector systems, backed with liquid ring pumps, have been used. However, these are energy inefficient, rely on high steam quality for consistent performance, and cause foreline dust deposits that develop into “cakes” making cleaning difficult.

Steel degassing in tanks or in the ladle involves two basic processes: Vacuum Degassing (VD) and Vacuum Oxygen Decarburising (VOD). For these processes two types of vacuum pump system have been operated over the past 25 years.

1. The steam ejector system uses multi-stage high pressure steam ejectors usually supported by water sealed Liquid Ring pumps.

2. The alternative mechanical system uses multi-stage mechanical boosters supported by completely dry primary vacuum pumps.

The completely dry pump system has proven to be the most effective. The cost saving is significant, as shown over the page. There are also metallurgical benefits from the elimination of back-streaming of water vapour. Combined with the better ultimate vacuum, this leads to reduced residual hydrogen in the metal. Faster evacuation and more flexible operational characteristics allow for closer chemistry control. This leads to more consistent formulation and opportunities for new steel qualities.

All maintenance costs are reduced, including cost for cleaning the pumps and pipework. The waste disposal costs for the dry dust are also reduced, or the dust can be recycled reducing costs further and limiting the impact on the environment.

### Why mechanical pumps?

- Cost saving
  - Energy costs reduced by over 90%
- Reduced maintenance
  - Elimination of fore line deposits
- Reduced effluent costs
  - Easier disposal or recycling of dry waste
- Reduced cycle times
  - Vacuum on demand
- Consistent processing
  - Reliable and dependable vacuum level
- Better steel quality
  - Lower hydrogen levels achieved in VD
- Improved stainless quality
  - Better VOD control
- New steel qualities
  - Easier control of chemistry



application note

**EDWARDS**  
Vacuum science... product solution.

### Operating cost comparison:

Dry mechanical vacuum pumps vs. steam ejectors

Melt mass (tonnes) = 60

Boiler size (kg/h) = 10000

Production tonnage = 300.000

Process = VD

Cycle time in vacuum (mins) = 25

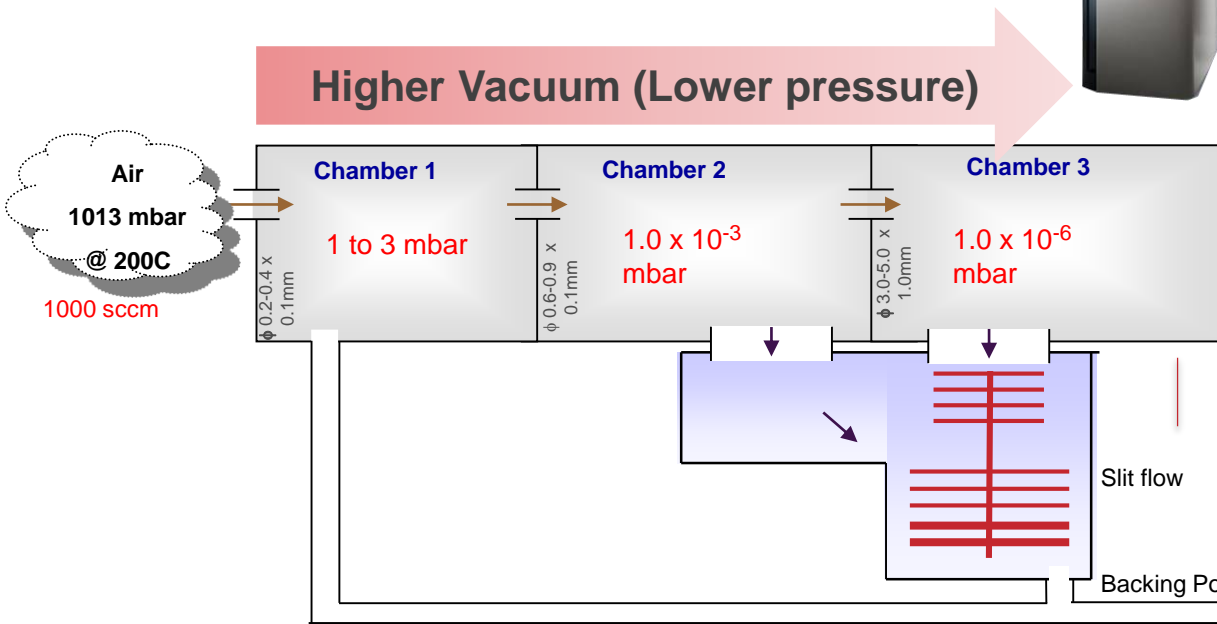
Cost criterion	Condition	Specific cost	Steam ejectors	Dry running pumps including filter operating costs
<b>Consumption</b>				
- steam	12 bar, 194°C	20,00 €/t	69,4 kg/t 1,3888889 €/t	
- contact water	3 bar, 32°C	0,04 €/m <sup>3</sup>	4,3 m <sup>3</sup> /t 0,1805556 €/t	
- non-contact water	4 bar, 32°C	0,03 €/m <sup>3</sup>		0,0875000 m <sup>3</sup> /t 0,0026250 €/t
- compressed air	3 bar	0,02 €/m <sup>3</sup>		0,0002500 m <sup>3</sup> /t 0,0000050 €/t
- nitrogen	3 bar	0,10 €/m <sup>3</sup>		0,0550000 m <sup>3</sup> /t 0,0055000 €/t
- gear box oil		3,00 €/liter		0,0004400 liter/t 0,0013200 €/t
- power (pumps+auxiliaries)		0,05 €/kWh	0,69 kWh/t 0,0347222 €/t	0,3750000 kWh/t 0,0187500 €/t
Subtotal consumption			1,6041667 €/t	0,0282000 €/t
<b>Maintenance</b>				
	€ per hour	man hours		
- pump service	35,00	4	140,00 €/pump	5000 tappings 0,0014000 €/t 5000
- pump cleaning	35,00	40	1400,00 €/job	200 tappings 0,1166667 €/t
- heat exchanger cleaning	35,00	12	420,00 €/job	5000
- filter bag changing	35,00	8	280,00 €/job	2083
- dust disposal			0,00 €/t	0,00 kg/t 0,0000000 €/t 0,20
- contact water disposal			1,00 €/m <sup>3</sup>	0,45 m <sup>3</sup> /t 0,4513889 €/t
Subtotal maintenance				0,5694556 €/t
<b>Spares</b>				
	€ each	number		
- filter bags	15,00	216	3240,00 €/charge	0,0000003
- seals and bearings	2000,00	per installed pump	3 pumps 0,0100000 €/t	9
Subtotal spares				0,0100000 €/t
TOTAL				2,1836222 €/t
Difference				0,0000000 €/t
Annual saving				

Operating costs	Steam ejectors	Dry running pumps including filter
	€/ton	€/ton
Energy and fluids	1,6041667	0,0282000
Maintenance	0,5694556	0,0042014
Spares	0,0100000	0,0300000
TOTAL	2,1836222	0,0624014
Saving	0%	97%





# LCMS - QUADRUPOLE



## What types of LCMS are there?

Single quadrupole	1,500 - 3,000 amu	Simple ↓ Sophisticated
Ion trap	1,500 - 3,000 amu	
Triple quadrupole	1,500 - 3,000 amu	
Time of Flight	15,000 - 20,000 amu	
Quadrupole Time of Flight	16,000 - 30,000 amu	
FT Ion Cyclotron Resonance	40,000 - 50,000 amu	

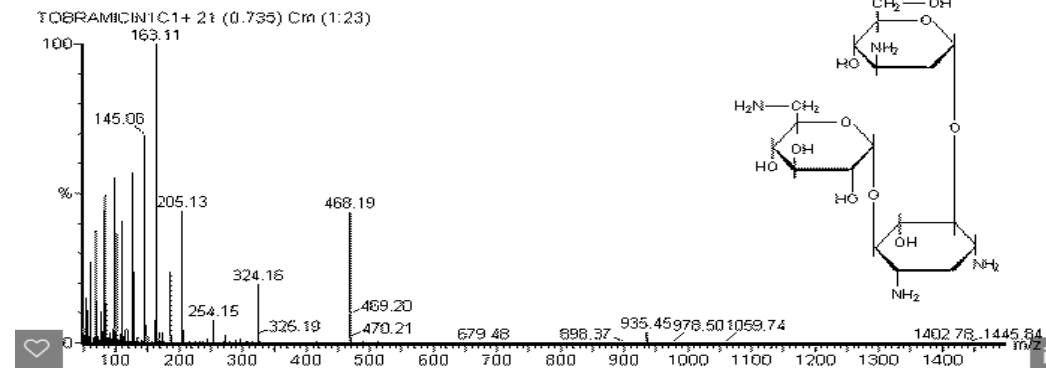
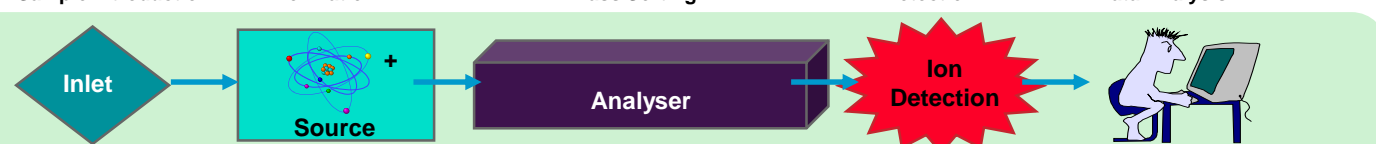
High vacuum conditions prevent collisions of ions with residual molecules in the analyser during the flight from the ion source to the detector: they increase the efficiency of ion transfer and detection



The function of a primary pump is to operate as a backing pump for the turbo-molecular pumps(s) and to remove carrier gas and/or solvent carry over



Sample Introduction    Ionization    Mass Sorting    Detection    Data Analysis



# LCMS VACUUM HISTORY: 1990S – 2000S – 2016/FUTURE



## Secondary pumps: TMPs

Replaced Oil diffusion pumps: no 'accidents'  
and lower CoO (power)

Move to fewer discrete TMPs: lower system  
and service costs = higher 'up-time'

- Communications protocols
- Modelling – fewer iterations on NPI

## Primary pumps

'Wet' to 'dry' pumps – smaller (then larger)

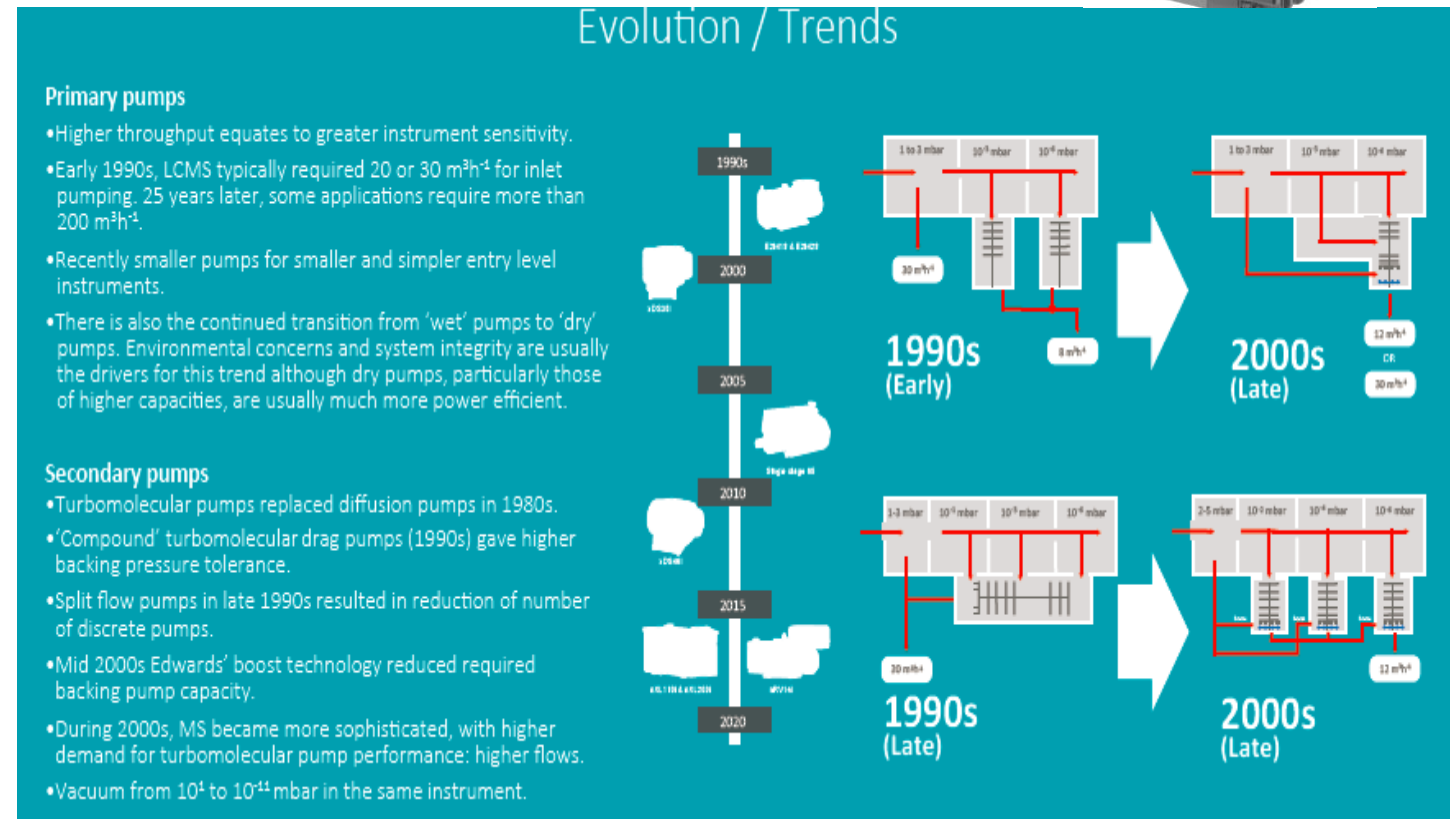
Lower power = low heat generation

and lower CoO

No oil to dispose of

Local service possible

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# LCMS TMP CONFIGURATIONS



**Spectroscopy**  
Solutions for Materials Analysis

### Considerations for Primary Vacuum Pumping in Mass Spectrometry Systems

Mass spectrometry systems have specific vacuum requirements. New developments in oil-free, or dry, primary vacuum pumps have been introduced recently and are discussed in this article with respect to capacity, throughput, and specific pumping requirements for process gases.

A.D. Chew, A. Cameron, D. Goodwin, J. Hamilton, T. Hawley-Jones, P. Meares, J. Pumfrey, J. Ramsden, and D. Steele

There are many drivers for vacuum configuration in mass spectrometry (MS) and other scientific instrumentation applications. These include vacuum performance of the primary pump itself (speed, compression, power, and so forth), environmental impact, power, construction, service interval, and the requirements (if any) for oil, regulatory compliance, cleanliness of the vacuum produced, and compatibility with process and target gases-vapors.

MS systems have very specific vacuum (physics and engineering) requirements. The systems primarily considered here are liquid chromatography-MS (LC-MS), gas chromatography-MS (GC-MS) and inductively coupled plasma MS (ICP-MS). New developments in oil-free (dry) primary vacuum pumps have been introduced recently to the scientific instrument user markets and their impact is discussed below.

**Specific Vacuum Requirements**  
There are several performance requirements for vacuum systems used with mass spectrometers.

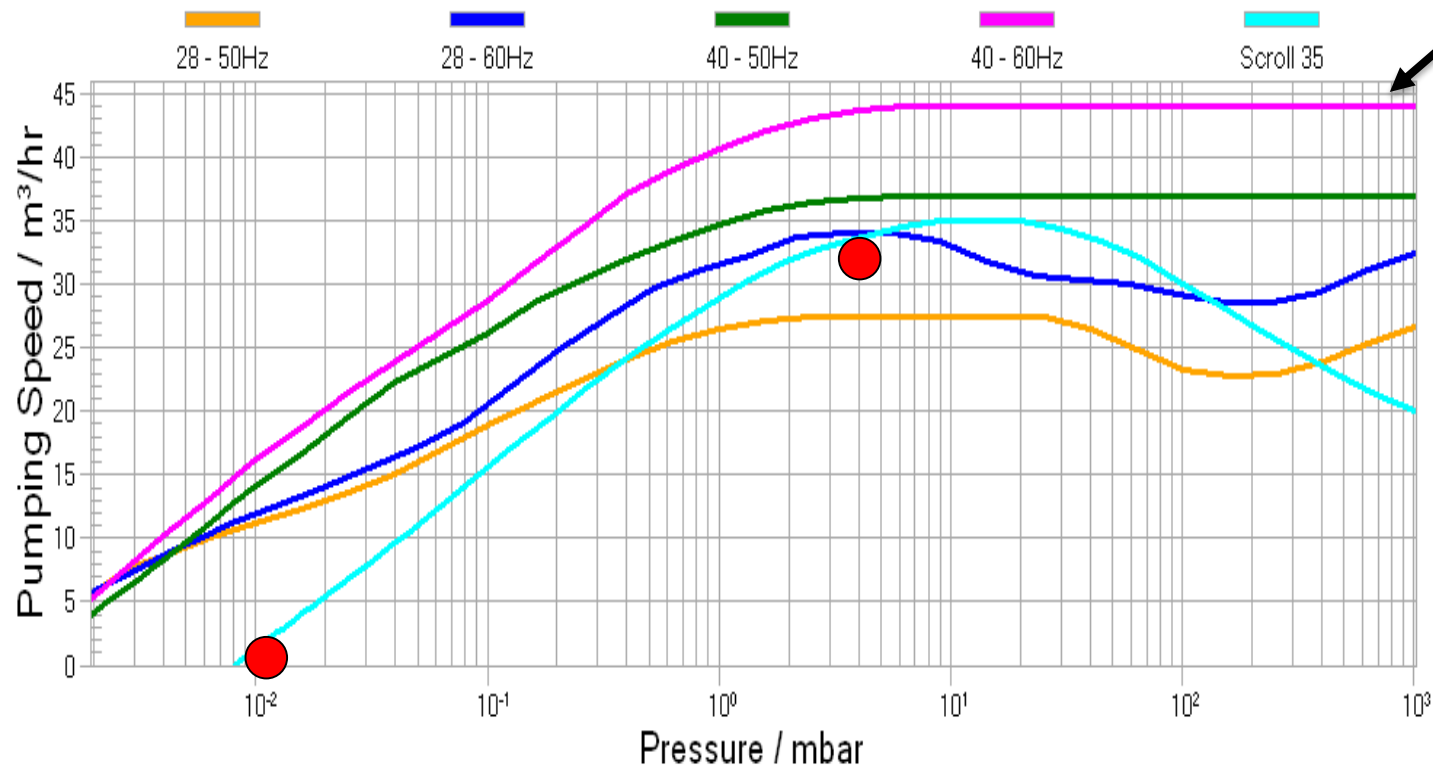
**Capacity.** This refers to the maximal pumping speed of the pump or, more importantly and specifically, the throughput for process-target gases (carrier, collision, and shield) at a nominal process pressure. This might be to provide a sufficiently low backing pressure for a turbomolecular pump when the process gas line shares the backing line of a turbomolecular pump.

Alternatively, the pump might be required to create a stable inlet-process pressure, for example, at the source. Other specific pumping requirements include resistance to gas permeability, for example, in the pumping of helium. The permeable nature of helium is such that a latent signal of helium, or drift in the inlet pressure, can occur in pumps of

Figure 1. XDS55 Scroll Pump.



# PUMPING SPEED COMPARISONS: SCROLL - OSRV



● Design points for LCMS

now > 100 m<sup>3</sup>/h



nXL110i/nXL200i

- 25 slm
- higher throughput = higher sensitivity
- Air-cooled!

# CAT 1 LRP: STYRENE DEVOLATIZER SYSTEM



# LEGISLATIVE REQUIREMENTS - ATEX ETC.

- ATEX is a European directive **2014/34/EU** 'Equipment and protective systems intended for use in potentially explosive atmospheres



- IECEx is a **global certification** scheme, countries can chose to join

- Based on European EN standards, but with deviation



- Japan : Technology Institution of Industrial Safety

- Korea: Korea Gas Safety Corporation



- Brazil – INMETRO

All based on EN standards but with national deviations.

29.3.2014

EN

Official Journal of the European Union

L 96/309

DIRECTIVE 2014/34/EU OF THE EUROPEAN PARLIAMENT AND OF THE COUNCIL

of 26 February 2014

on the harmonisation of the laws of the Member States relating to equipment and protective systems intended for use in potentially explosive atmospheres (recast)

(Text with EEA relevance)

THE EUROPEAN PARLIAMENT AND THE COUNCIL OF THE EUROPEAN UNION,

Having regard to the Treaty on the Functioning of the European Union, and in particular Article 114 thereof,

Having regard to the proposal from the European Commission,

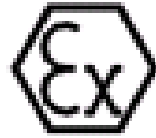
After transmission of the draft legislative act to the national parliaments,

Having regard to the opinion of the European Economic and

framework for the marketing of products <sup>(6)</sup> lays down common principles and reference provisions intended to apply across sectoral legislation in order to provide a coherent basis for revision or recasts of that legislation. Directive 94/9/EC should be adapted to that Decision.

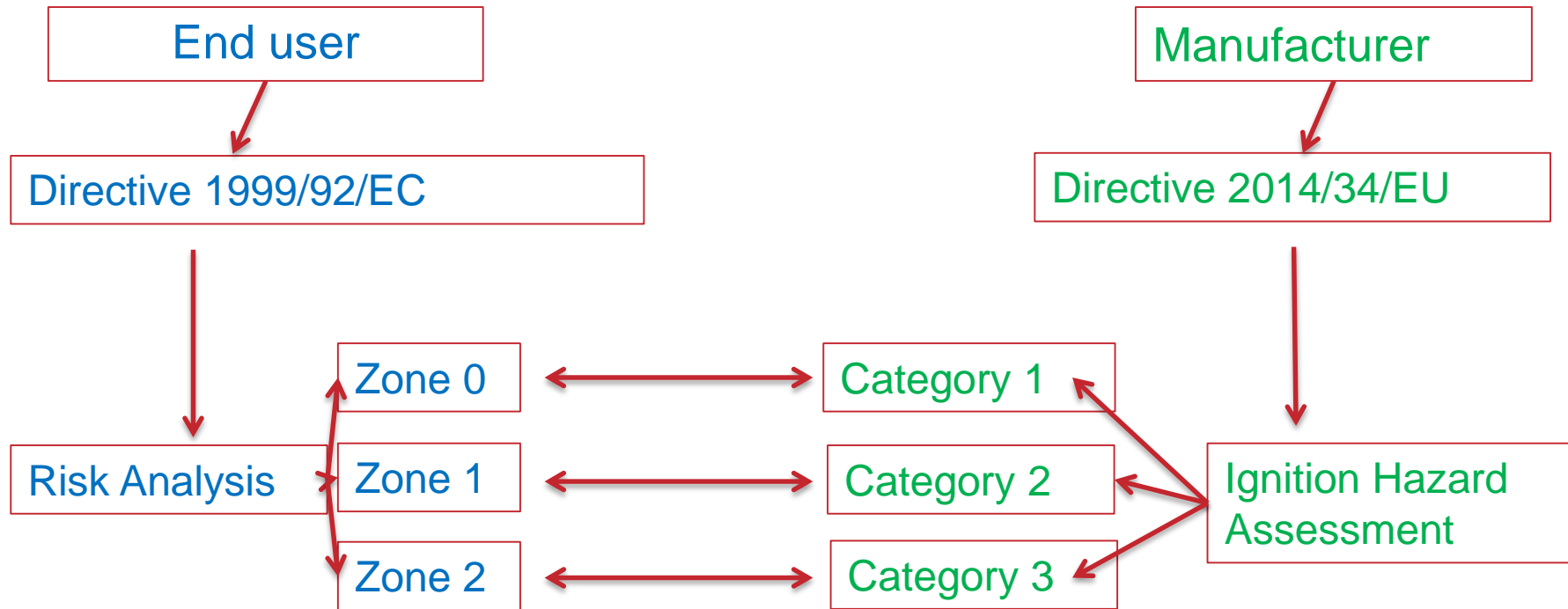
(4) This Directive covers products which are new to the Union market when they are placed on the market; that is to say they are either new products made by a manufacturer established in the Union or products, whether new or second-hand, imported from a third country.

(5) This Directive should apply to all forms of supply.

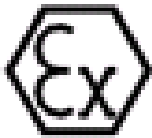


- Explosion: material reacts violently with Oxygen as the temperature rises
- **Deflagration**: Flame travels below or up to the speed of sound, the resulting explosion pressure is about 10 times the starting pressure
- **Detonation**: Flame travels faster than the speed of sound, resulting explosion pressure is far more than 10 times the initial pressure
  - **Zone 2**: an explosive atmosphere is not likely to occur during normal operation and if it does it is only there for a short period of time
  - **Zone 1**: an explosive atmosphere is likely to occur in normal operation occasionally
  - **Zone 0**: an explosive atmosphere is present continuously or for a long period









# II 2 G Exd [ia] IIB T4

Equipment Group;  
Group I: mining  
Group II: non mining

Important for Vacuum pumps:  
Internal and external marking  
required!

## Equipment Category

G = Gas, D= Dust

Ex d [ia] = protection concept, c = constructional safety, b = control of ignition sources

IIB = Gas Group

## Temperature Class T4

# FOOD – FATTY ACID DEODERISATION



# TOTAL RECIRCULATION LRP PACKAGES

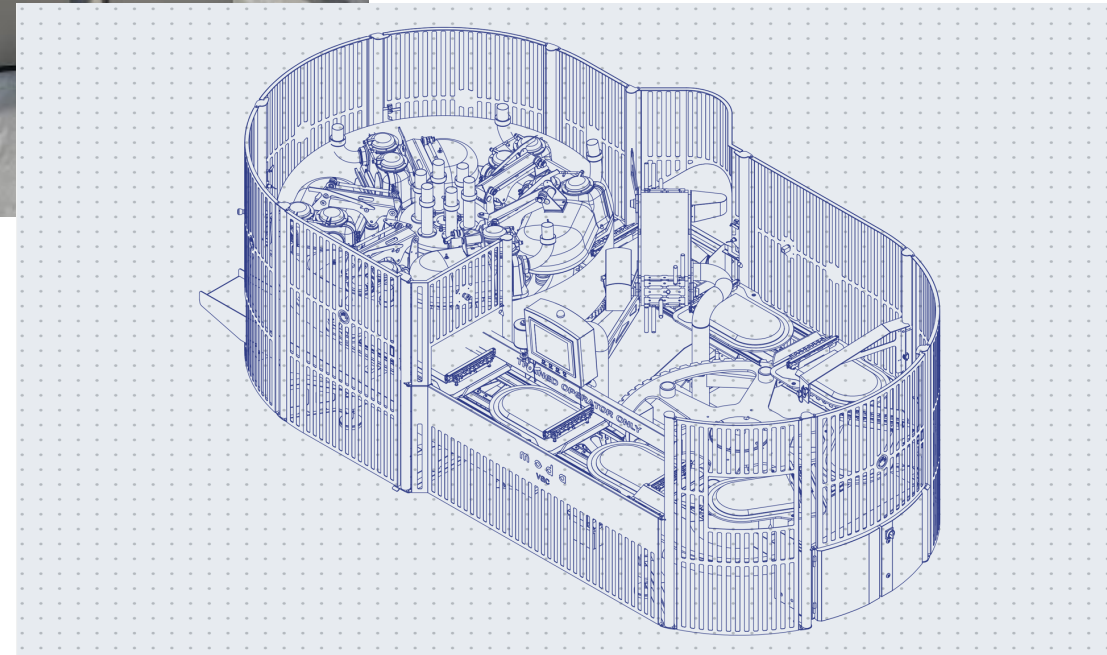
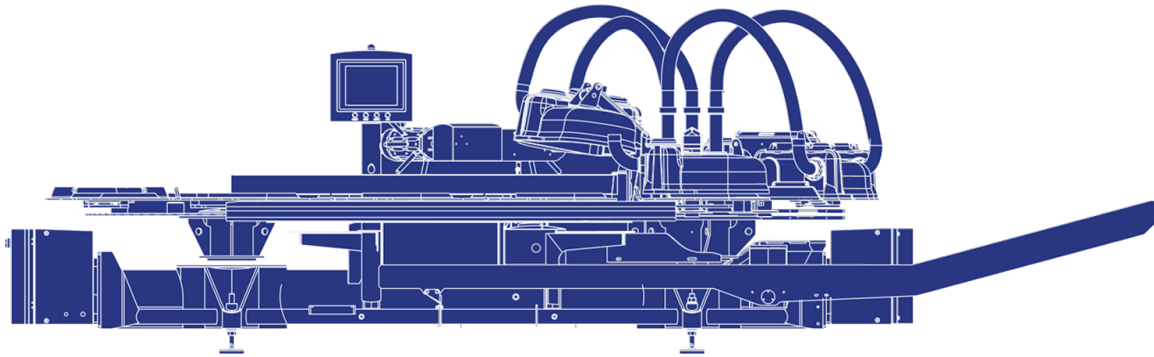


# OTHER (COATING) SYSTEMS ETC...



# FOOD PACKAGING

ModaVac New Zealand



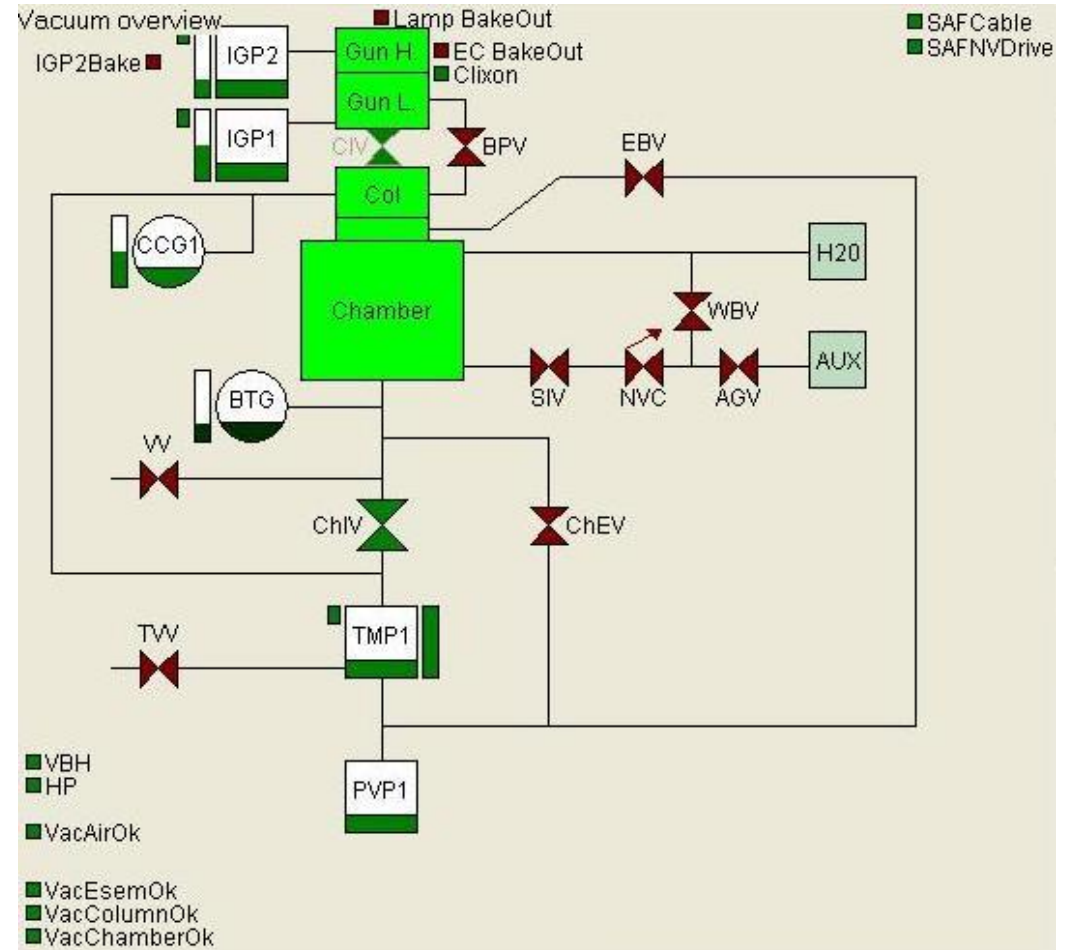
40–45 packs per minute @ 1.0mbar (0.75 torr)  
Stainless steel construction – T304  
6 chamber rotary indexing

# ELECTRON MICROSCOPY - SYSTEMS



<http://www.cvgs.k12.va.us/curric/SRSEM/emlab/svt.htm>

<http://www.tescan.com/gallery-gallery.php?menu=2>



Some use 'vacuum reservoir chamber'  
with TMP off during experiments

# ELECTRON MICROSCOPY VACUUM CONSIDERATIONS

- Typical EM electron m.f.p. ~1m @ 1e-4 mbar

Need lower pressures to prevent collisions with residual gas molecules

- At pressures  $<10^{-4}$  mbar – molecular flow regime: here conductance C of the pipe  $\sim r^3/l$
- Conductance is pressure independent

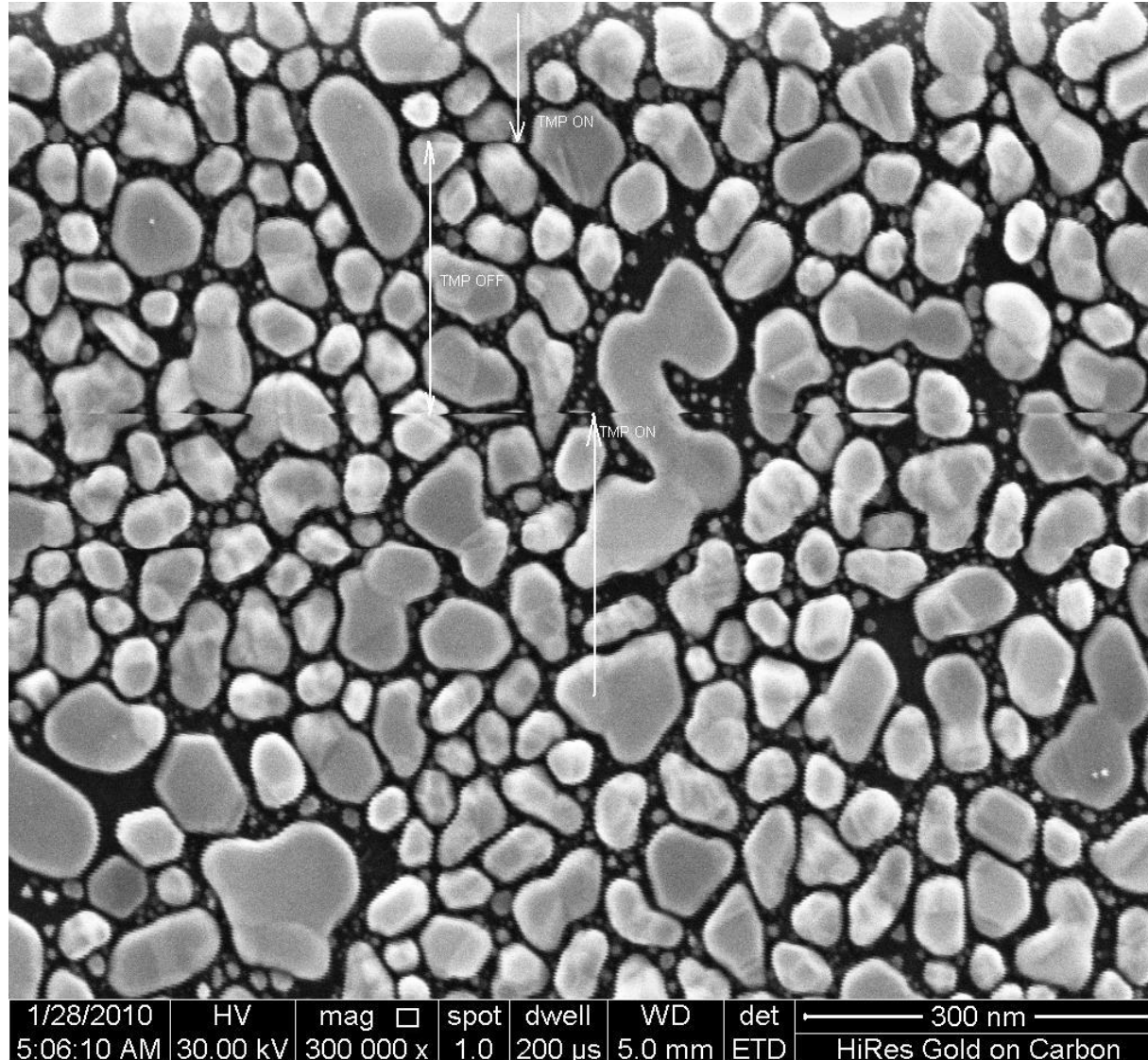
$$1/S_{\text{eff}} = 1/C + 1/S_{\text{pump}}$$

To maximise effective speed – minimise pump connections (use transmission probabilities for lower pressures)

Vacuum pumping system

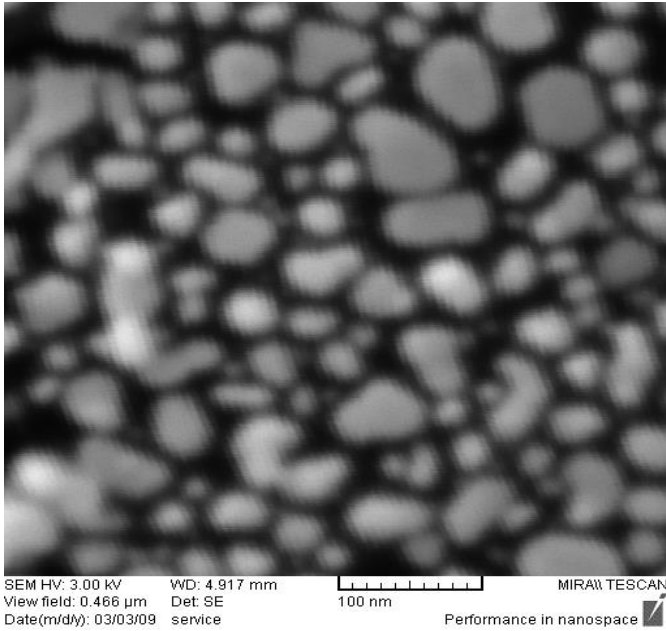
- Vacuum requirements vary: ~10 mbar to  $<1e-10$  mbar
  - Move from Diffusion pumps to TMPs (and Ion pumps)
  - Move from OSRV to dry primary pumps (scroll)
- 
- Vacuum pumps should not disturb images!

# ELECTRON MICROSCOPY - DISTURBANCE IN THE IMAGE

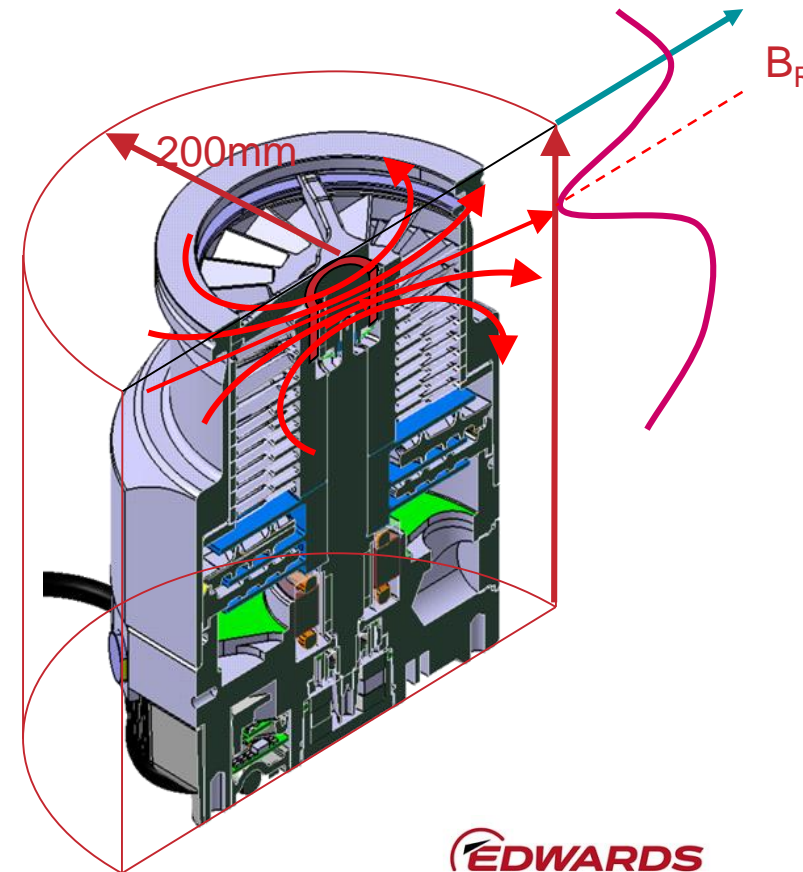


- Turbomolecular pump (and fan) are only mechanical part on a microscope
- Potential of
  - Mechanical vibrations
  - Electromagnetic field
  - Audible noise!





- More pronounced at low accelerating energies (Lorentz force)
- Use low field TMP versions ~ 0.1 to 1 mG  
c.f. Earth's field = 250 to 650 mG



# DRIVERS IN EM AND SURFACE SPECTROSCOPY –

## The future of electron microscopy

Yimei Zhu and Hermann Dürr

Physics Today **68**(4), 32 (2015)

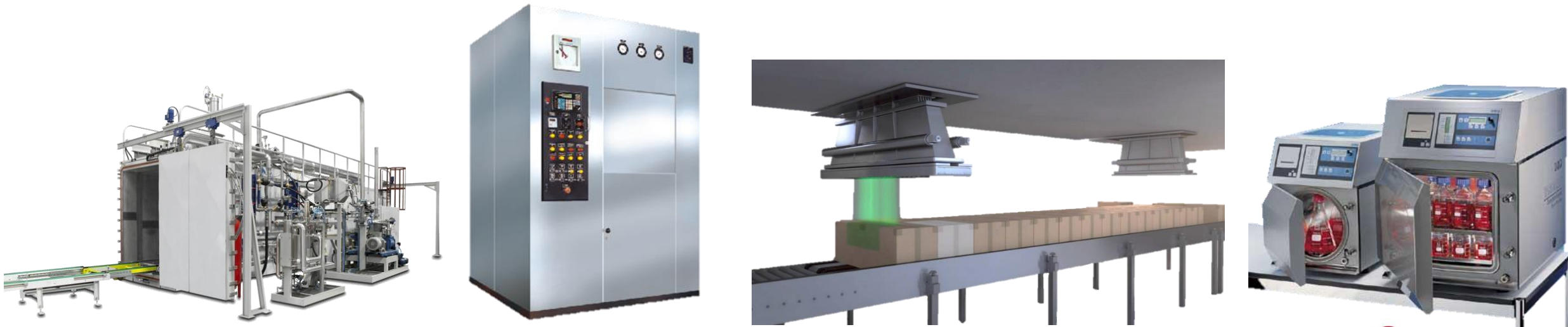
STEM allows analysis via other techniques

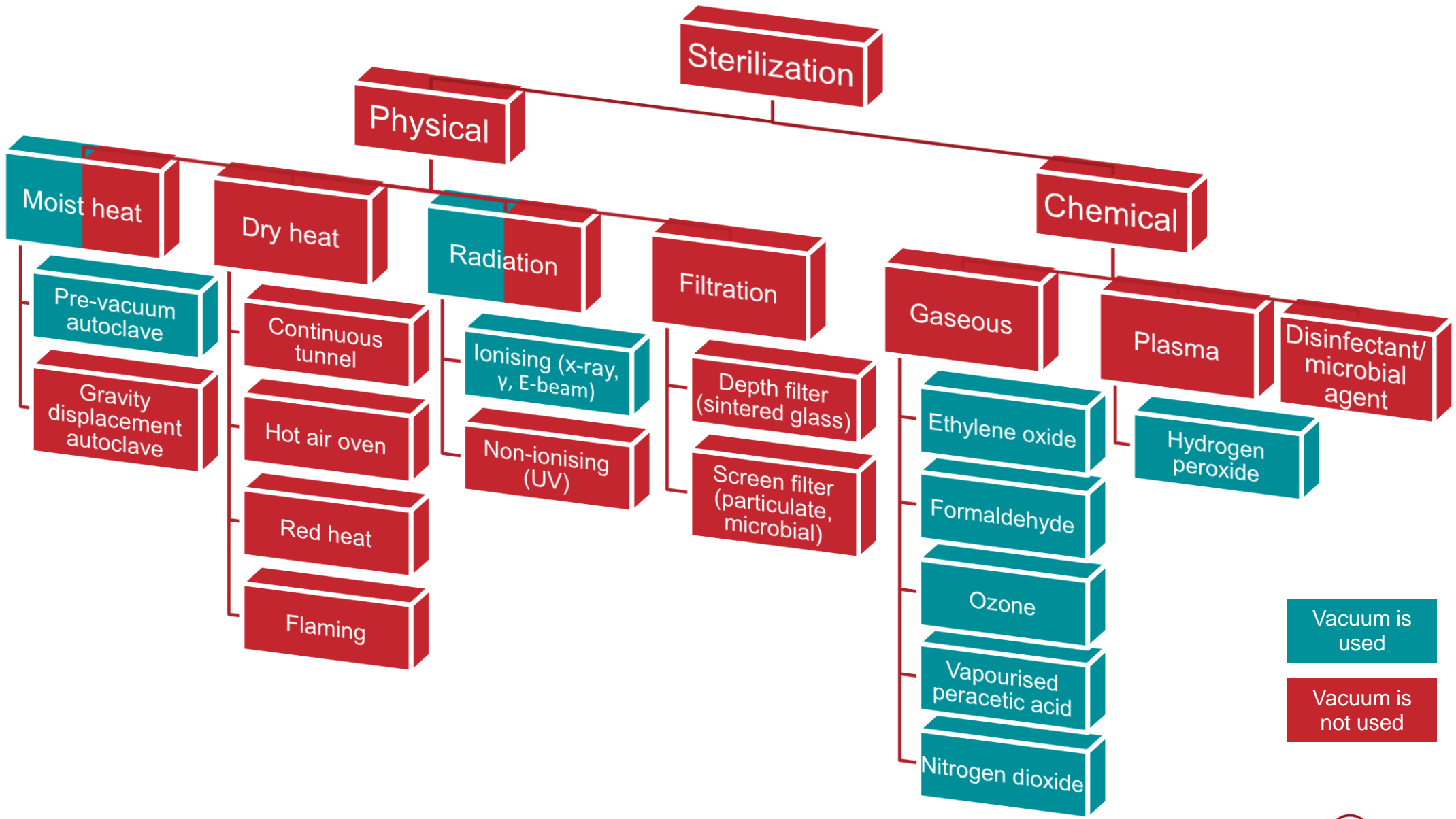
Secondary electrons, EDX, WDX, EELS

# STERILIZATION

*“The use of a physical or chemical procedure to destroy all microbial life, including highly resistant bacterial endospores”*

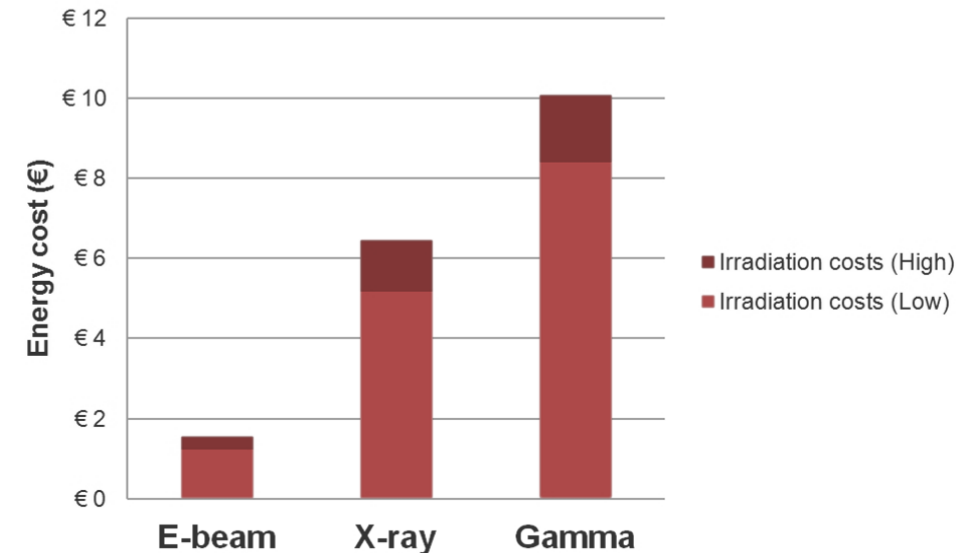
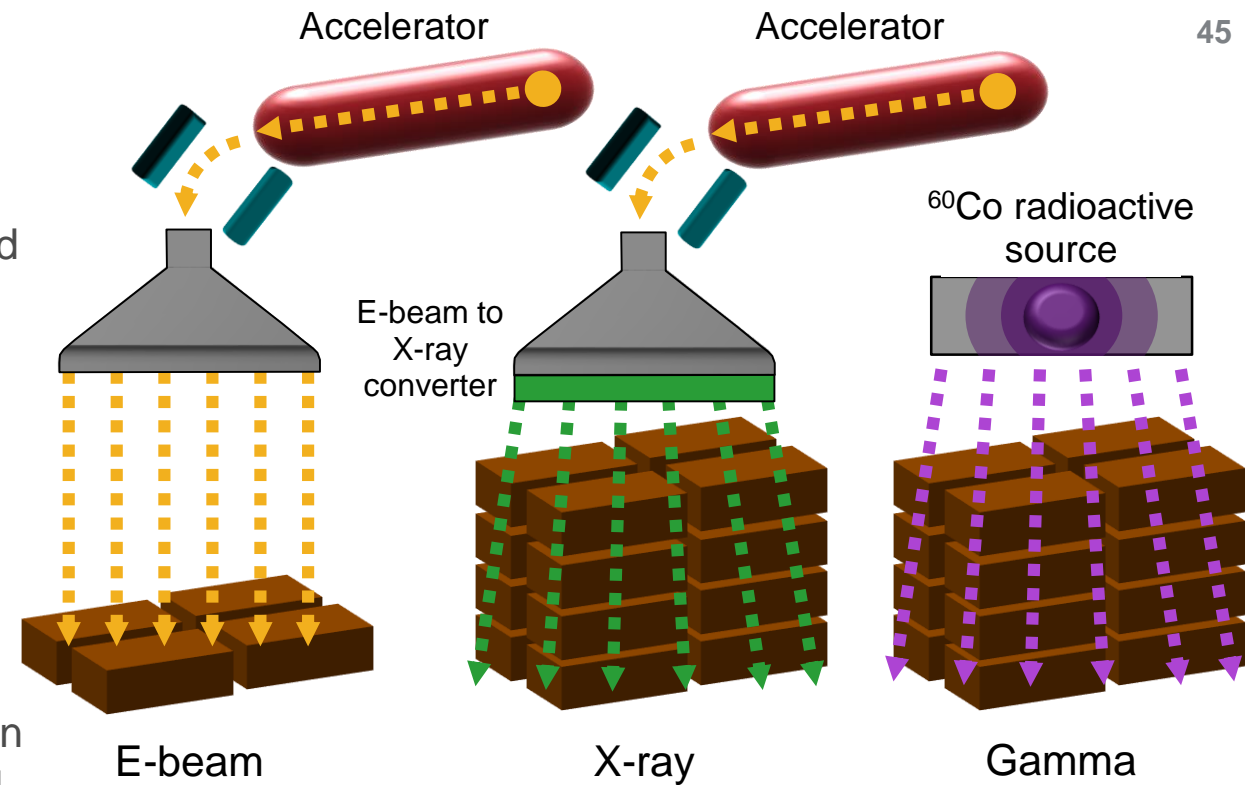
- It is a process commonly used in medical and food industries to ‘clean’ items of biological contamination and reduce the chances of infection and illness.
- Successful sterilization means no more than a one in a million chance that a microorganism will survive the process.





# RADIATION

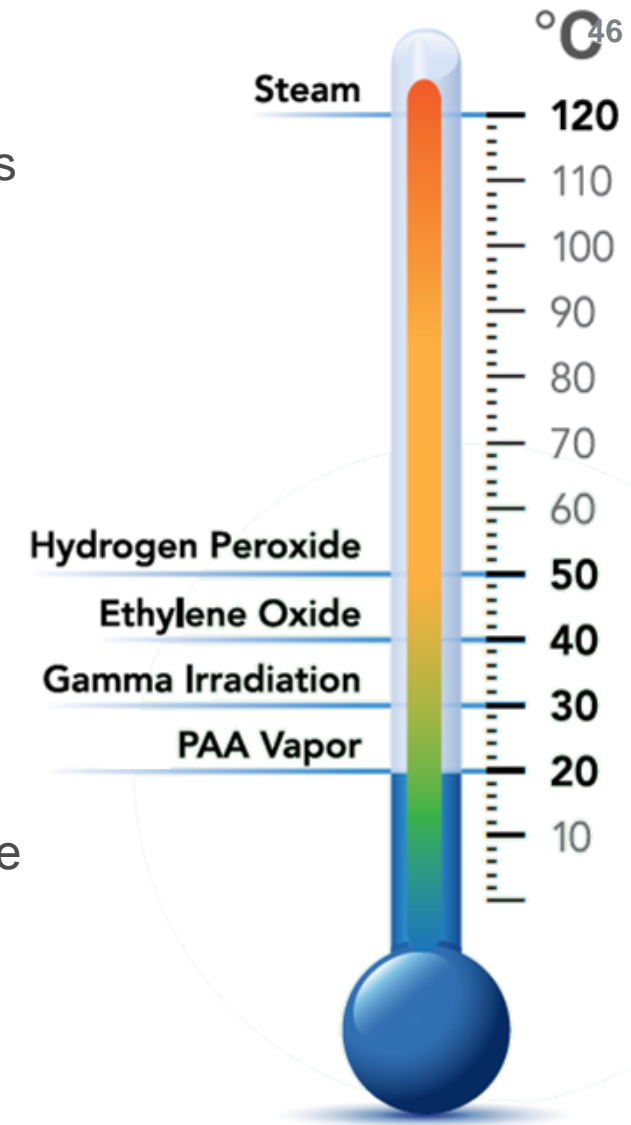
- Ionising radiation is **short wavelength** and **high-intensity** and causes damage to genetic material of microorganisms
- Sterilization by ionising radiation can use one of three techniques:
  - **Electron beam**
  - **X-ray**
  - **Gamma ray**
- Sterilization can also be done with **non-ionising UV** radiation but due to the longer wavelength this cannot penetrate and is only used on surfaces
- Ionising radiation sterilisation is a **low temperature** process which is used for heat sensitive items
- Compared with other low temperature processes it is relatively high cost so is generally used for large scale sterilization
- The use of ionising radiation is increasing due to the increasing power of electron accelerators



Cost of sterilizing 1m<sup>3</sup> with ionising radiation

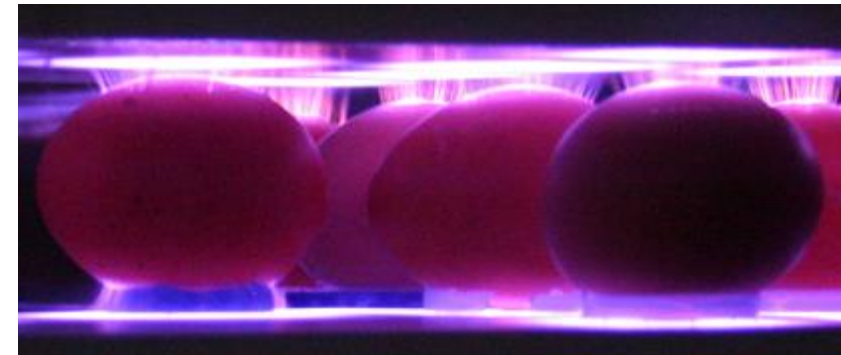
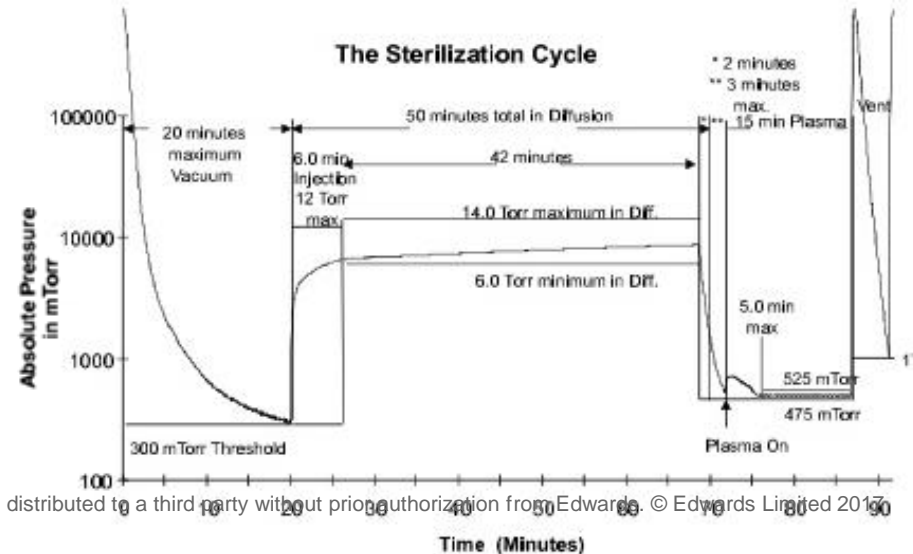
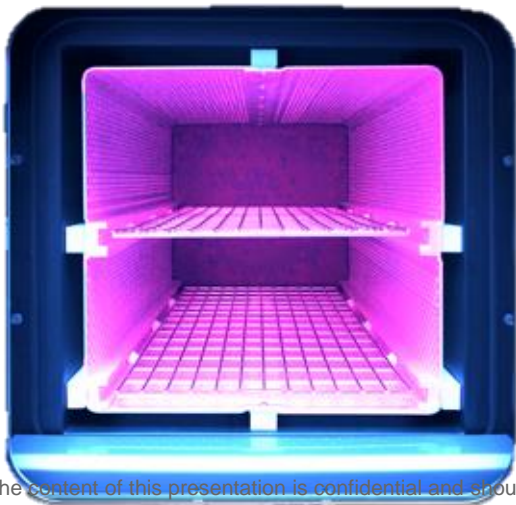
# GASEOUS

- Gaseous sterilization methods all use the same basic techniques with different gases injected:
  - Ethylene oxide
  - Ozone
  - Formaldehyde
  - Peracetic acid
  - Nitrogen dioxide
- The basic process for gas sterilization is **pre-conditioning** (air removal), **sterilization** (injection of gas) and **degassing** (removing gas and by-products)
- Generally gas treatments are '**low temperature**' and are often used for items sensitive to temperature
- Gas injection can be combined with steam sterilization to increase efficiency
- During treatment, temperature and pressure are controlled
- The active gases used for sterilization are often toxic, flammable or volatile and are therefore generally mixed with inert gases



# HYDROGEN PEROXIDE (AND OZONE) PLASMAS

- Plasma sterilization usually uses hydrogen peroxide ( $H_2O_2$ ) as the gas
- The  $H_2O_2$  is activated and produces a plasma of **charged particles** which glow visibly
- The plasma phase of  $H_2O_2$  is very effective, even at **low concentration** and **low temperature**
- The gas is vapourised and injected to the chamber under vacuum then an **electric field** is used to create the plasma
- Free radicals, IR/UV radiation and photon induced desorption lead to damage to the cells
- Many facilities are looking to replace EtO sterilizers with gas plasma however there are very few products available commercially, only small chamber volumes and worries over safety



# SOME THEMES AND DRIVERS

**Dry mechanisms** – no oil to be disposed of (risk of accidents, leaks (seal deterioration), spills and suck-back

**Lower Power**

**Smaller Footprint** – *backwardly compatible*

**Serviceability** (by end-user)

**Lower Cost-of ownership**

**Universal operation** - *inverter driven hence constant performance independent of supply voltage*

**Environmental**

**Life-time**

**Reliability**

**Safety/Legislation/ Compliance**

**Communications protocols**

**Modelling**



DPDS400/EH2600

@ CNRS, Grenoble since 2003  
with 0.76 g/s of helium at 10 mbar

**Lots of 'cross-selling' = cross-use**



# CONCLUSION

Vacuum enables many, many applications and technologies

There is no such thing as '*Just*' a Vacuum Pump

Systems are complicated and varied

Think where your vacuum skills could take you....

# THANK YOU



The CERN Accelerator School



CERN Accelerator School

in collaboration with

MAX IV Laboratory

are organising a course on

**Vacuum for Particle Accelerators**

# INDUSTRIAL VACUUM APPLICATIONS

## - A VERY PERSONAL PERSPECTIVE

DR ANDREW CHEW

SATURDAY 10<sup>TH</sup> JUNE

